

Photonic Quantum Technologies

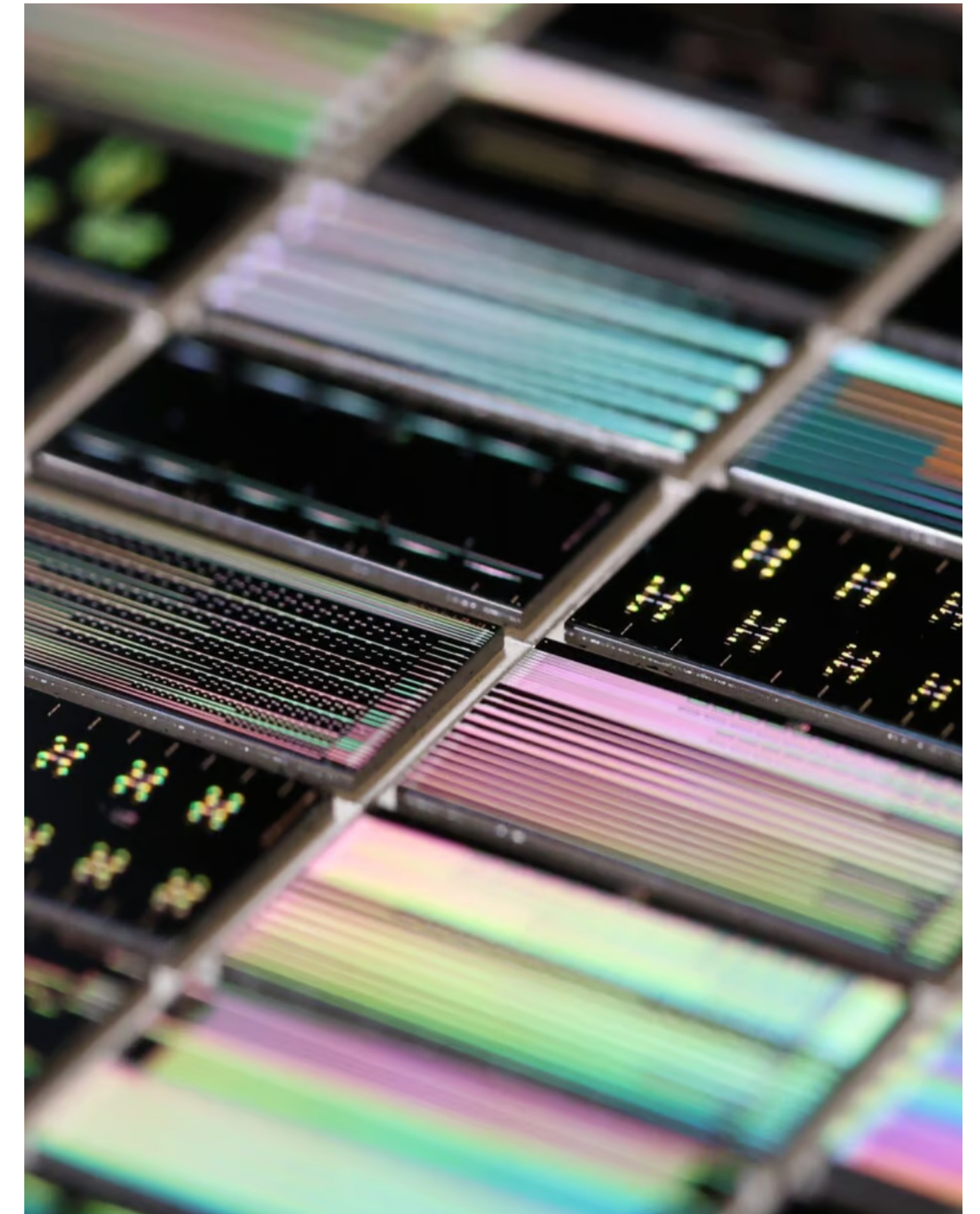
Dr. Michael Förtsch

Founder & CEO

24. June 2024

Prepared for SOC Summer School 2024

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Q.ANT

Q.ANT

Short Introduction

Fast development and prototyping led us to 3 World Premiers
made possible by a strong expert team, partner landscape and IP portfolio.

2018

Foundation

4

Product Lines

2.300

sqm Workspace

100+

Q.ANTies

17

Nationalities

6

Publicly funded
projects

51

Patent Families

3

World Premiers ^{1,2}

7

Coffee machines³

¹www.produktion.de/technik/zukunftstechnologien/quantentechnologie/erste-industriefaehige-quantensensoren-sind-im-einsatz-44-344.html

²gant.com/press-releases/q-ant-presents-the-potentials-of-quantum-technology-at-the-hannover-fair/

³Our fast pace took toll on 7 coffee machines thus far ;)

Q.ANT backbone is its Photonic Framework Para.Digm ...

... realizes the next level of data generation and data processing.

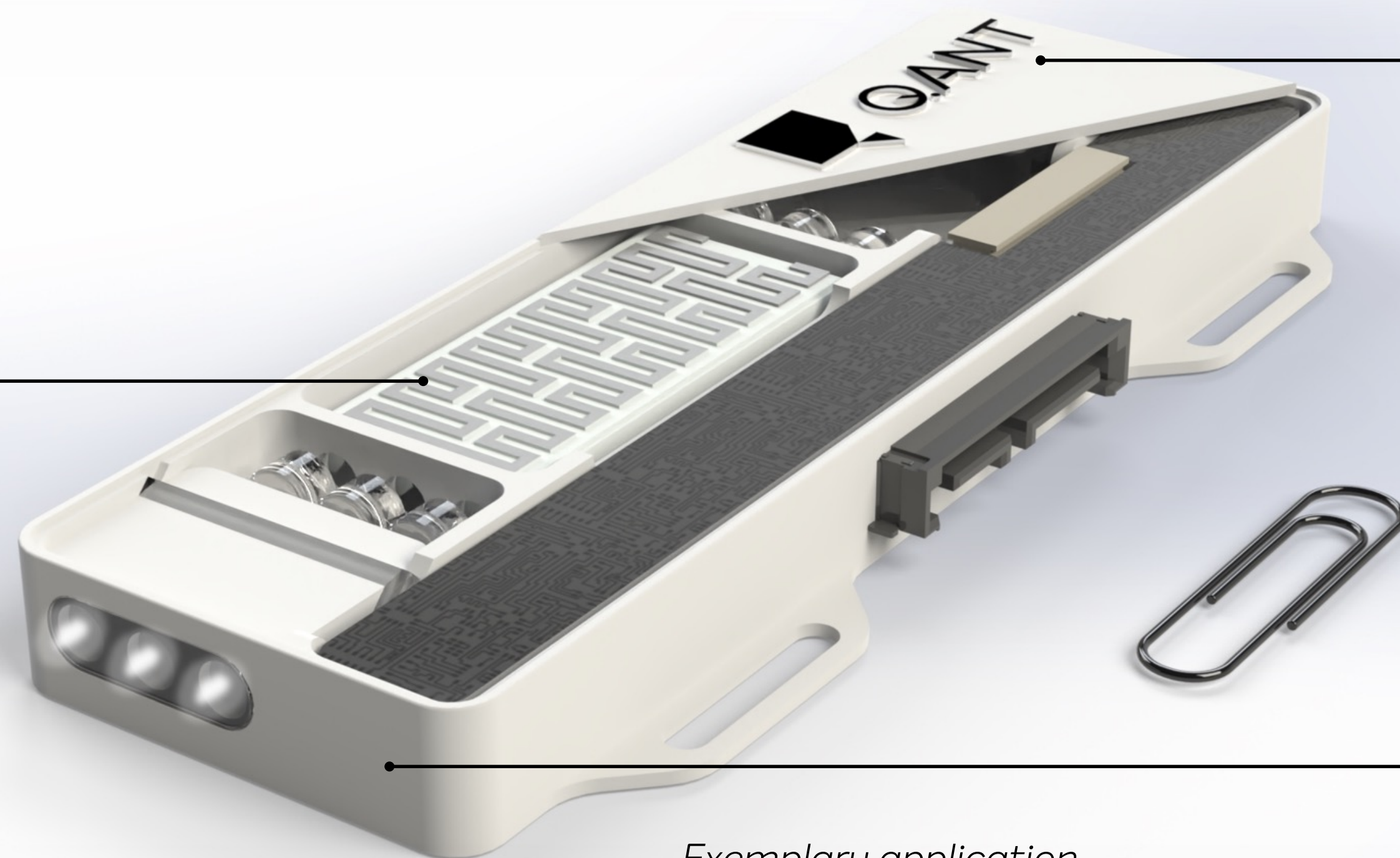


Electron to photon conversion

- Solid state diodes
- Low-noise current drivers

Quantum controls

- Nonlinear waveguides
- Tailored optical elements



Exemplary application

Photon to Electron conversion

- Low-noise amplifiers
- Analog to Digital conversion
- Signal process

Q.ANT realizes the next level of data generation and data processing in the following four product lines

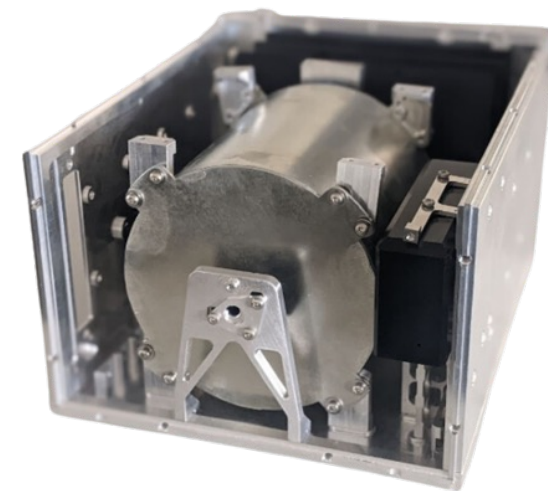
Data generation

Particle Metrology



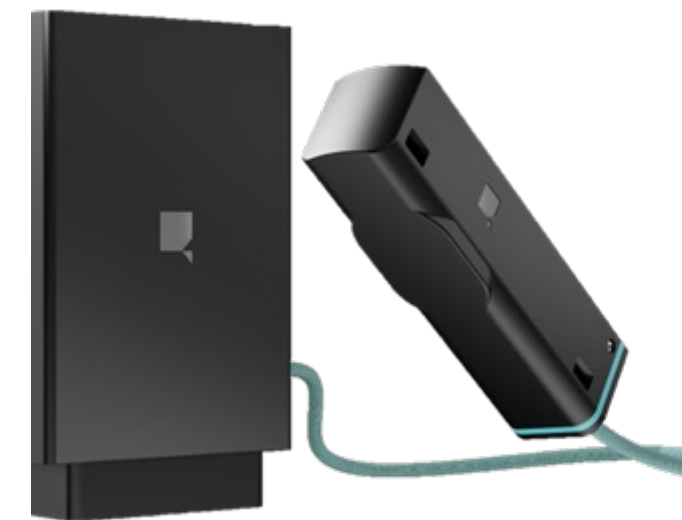
Sensor for analyzing finest particles in gases, liquids and as powders.

Atomic Gyroscope



Sensor for stabilization and localization of systems.

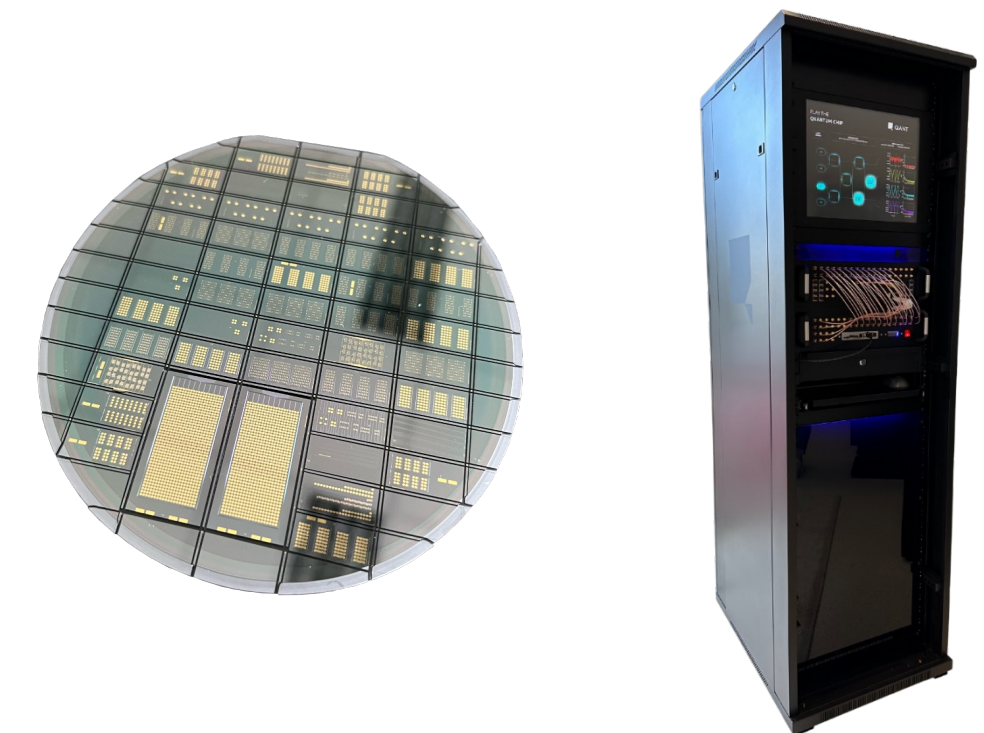
Magnetic Sensing



Sensor for measuring electrical bio signals

Data processing

Photonic Computing



Photonic chips and computing for solving complex algorithms.

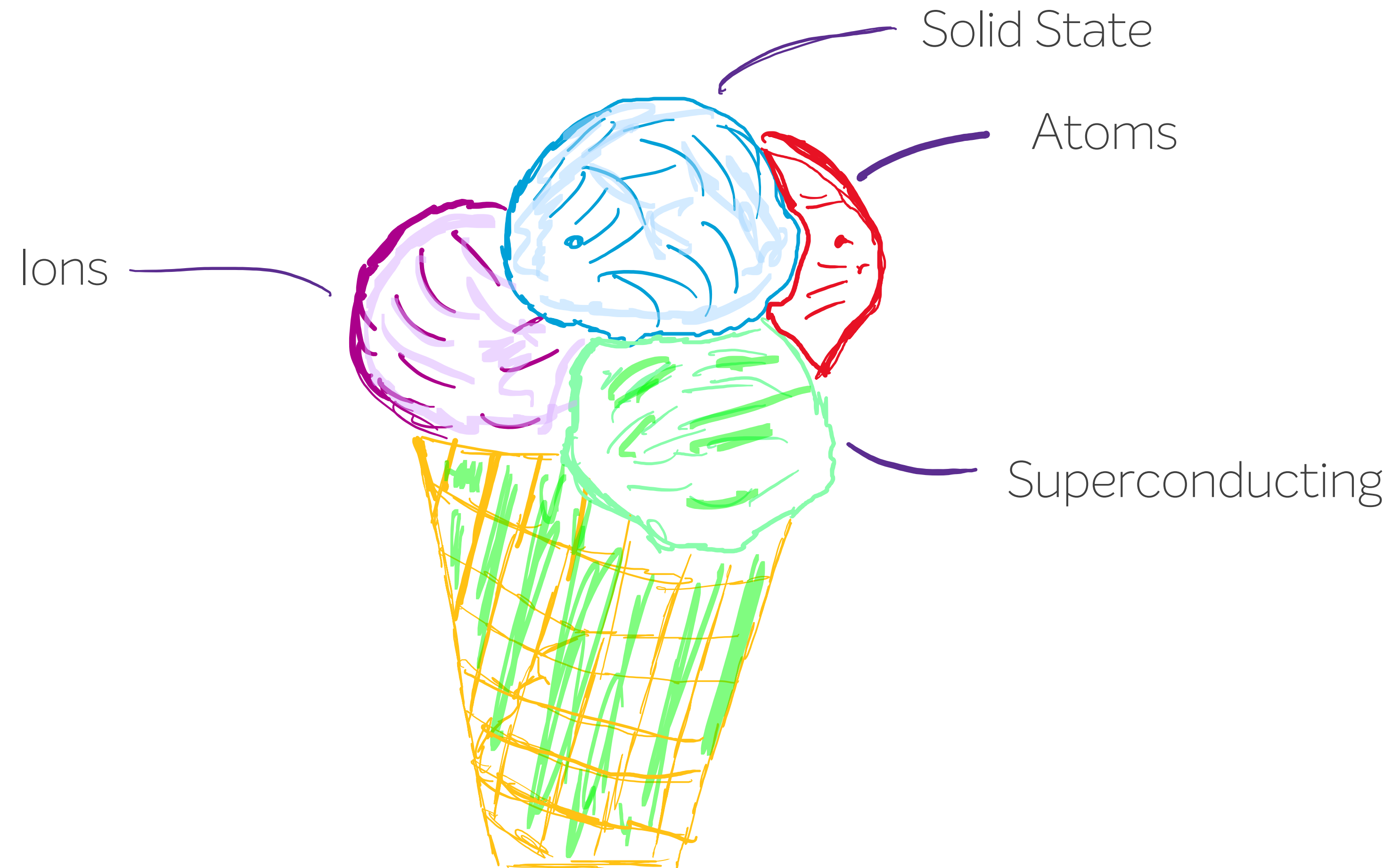
Our new magnetic field sensor was a big attraction on the Hannover fair 2024
with a live detection of muscle signals, bringing humans and machines closer.



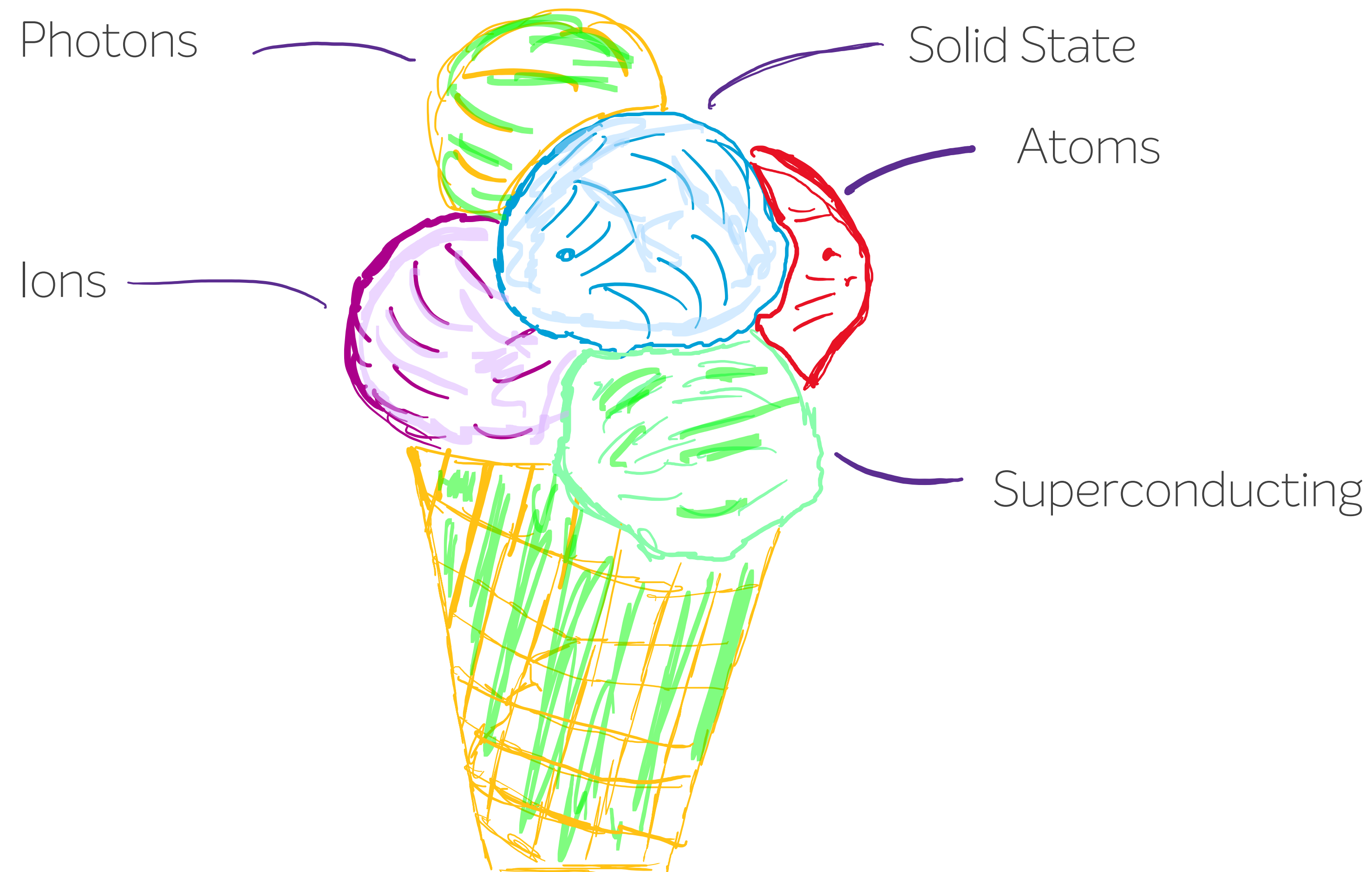
Photonic Computing

For Classic and Quantum

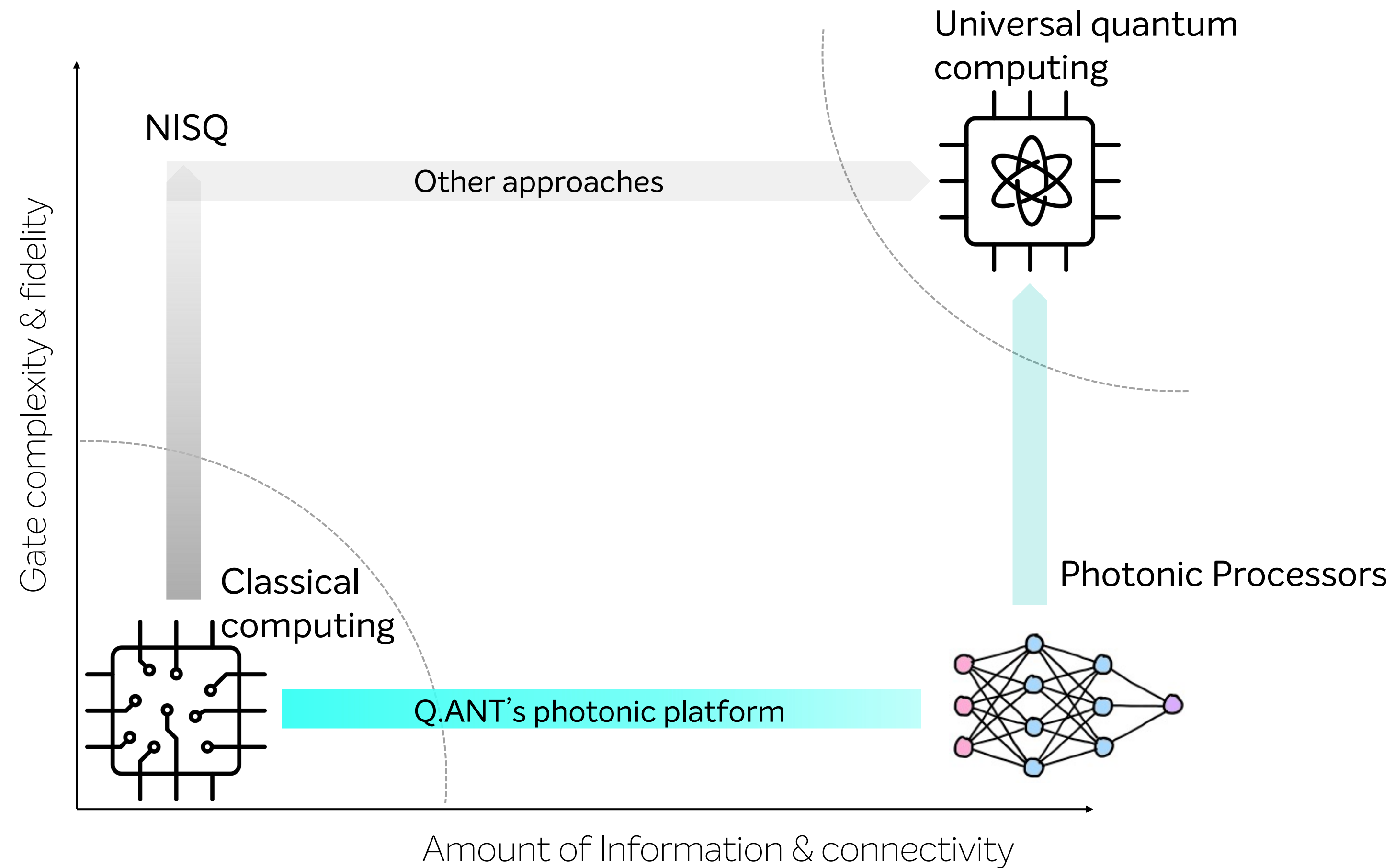
Many approaches are racing towards a productive Quantum Computer.



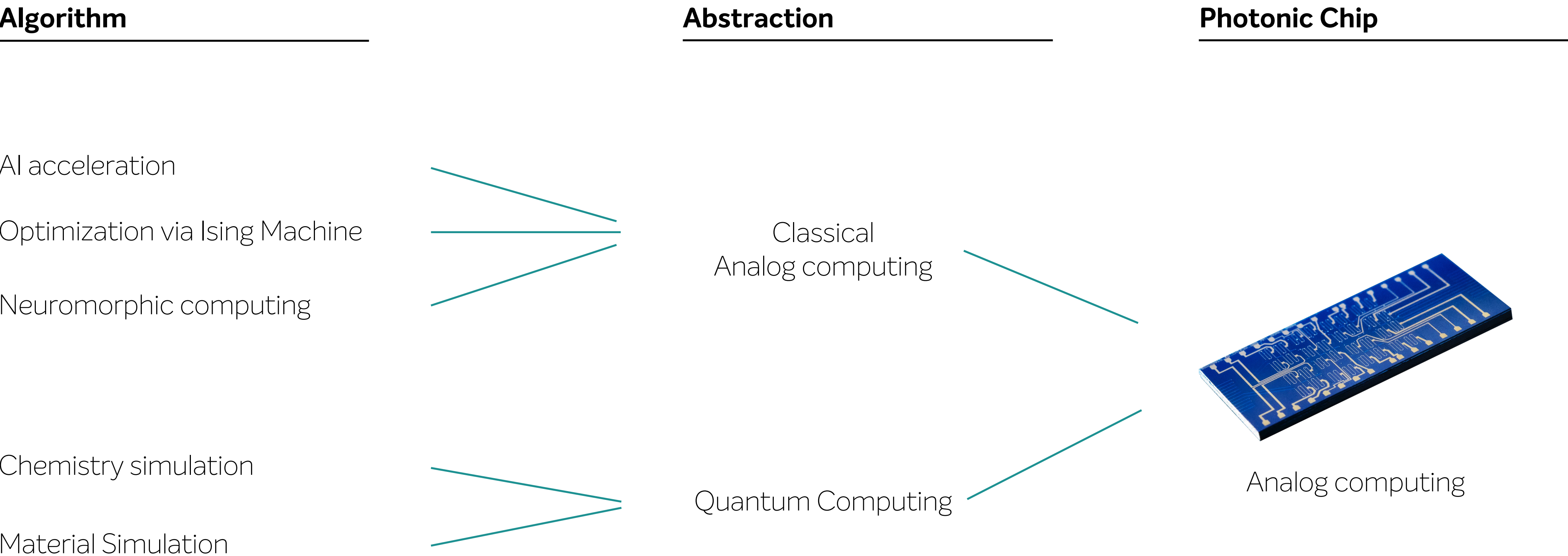
Do we need an additional platform based on Photons?



Photonic Computing is a novel approach to the next level of computing.

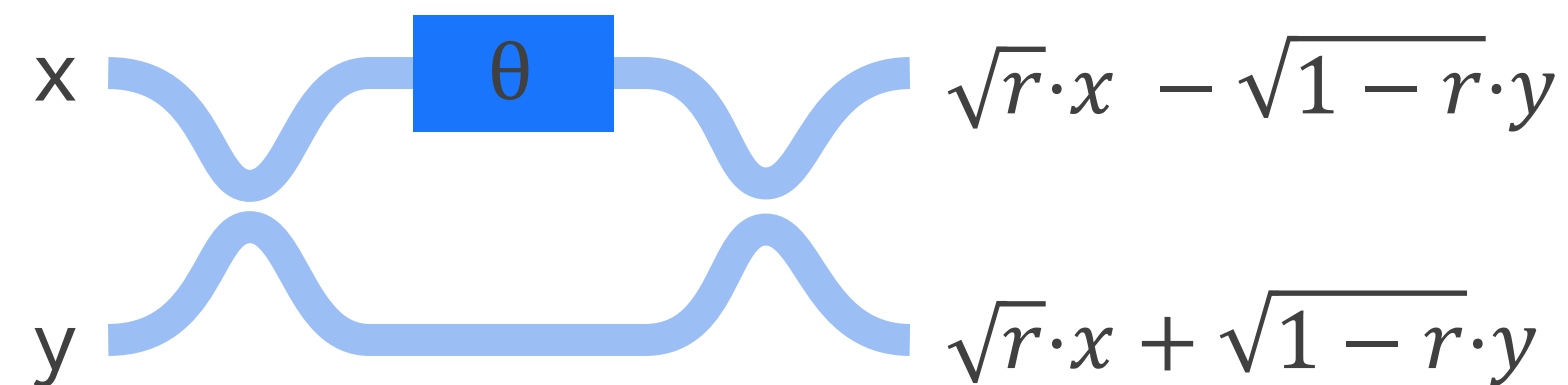


One technology – multiple applications for data processing
Photonic integrated chips open up a wide range of applications.

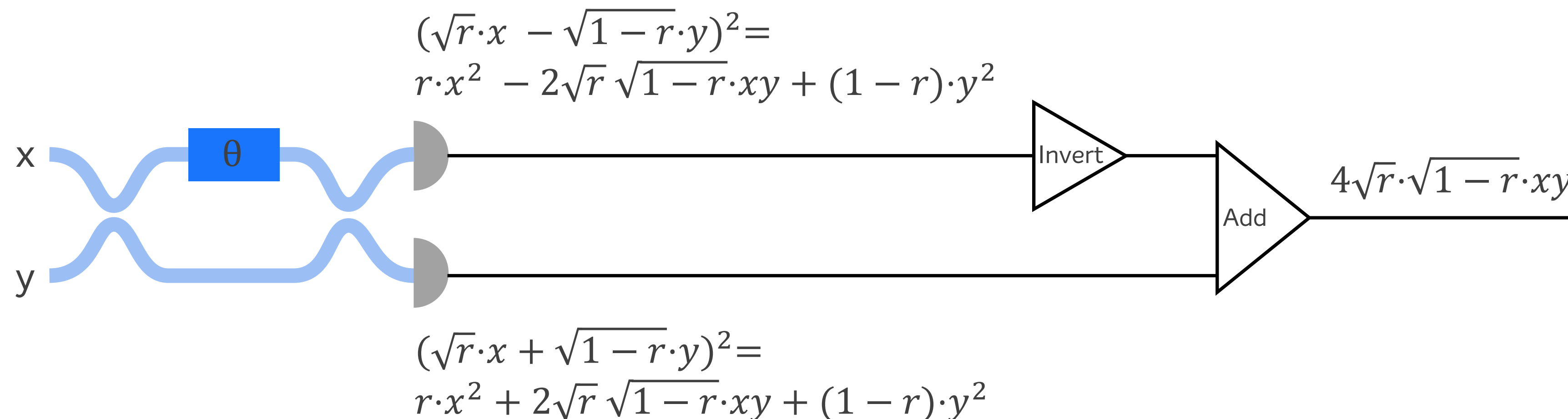


Photons natively implement addition/subtraction as well as multiplication

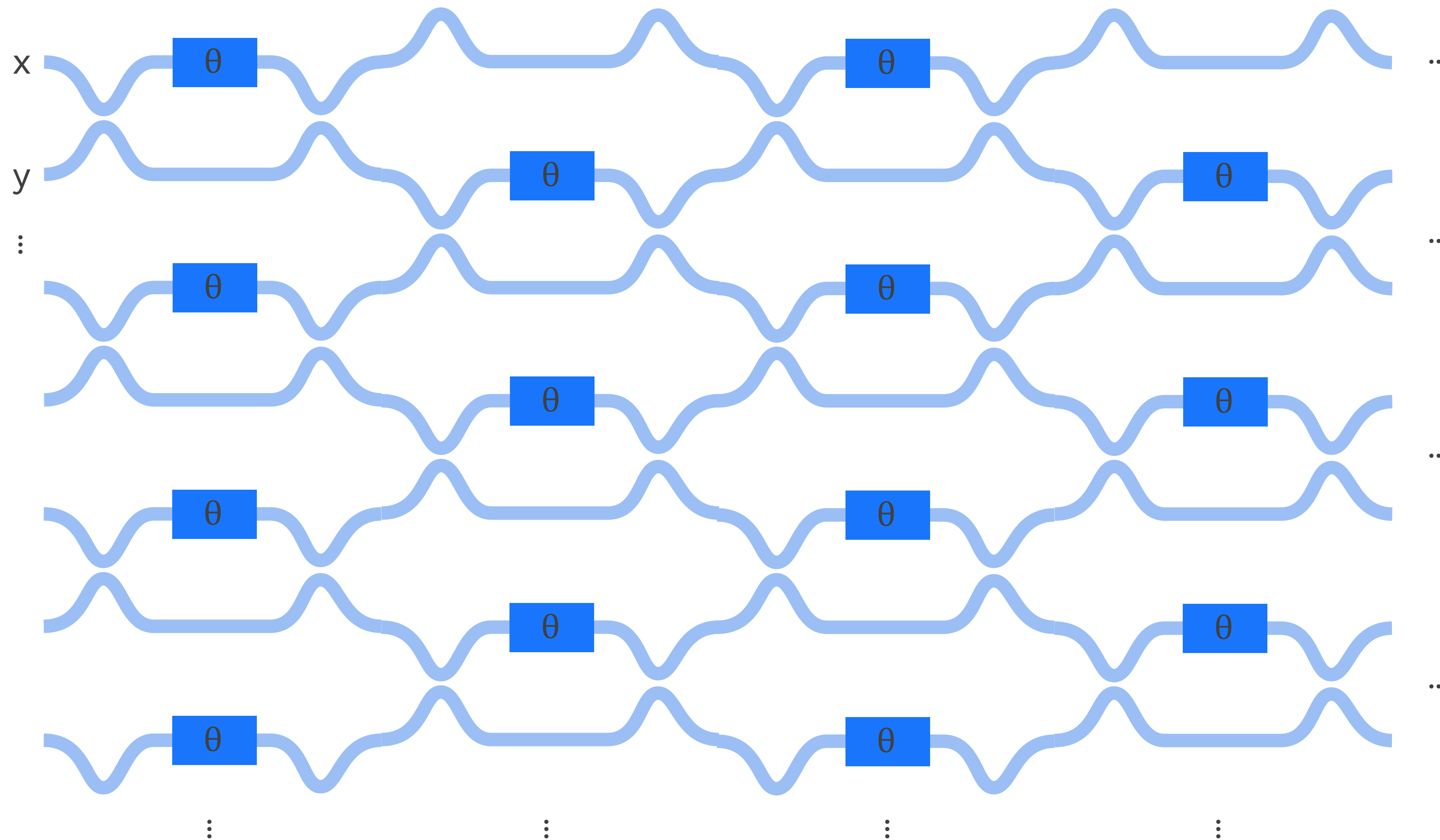
Variable beamsplitters natively add and subtract the two inputs in parallel



Detectors natively square the inputs, implementing several multiplications in parallel

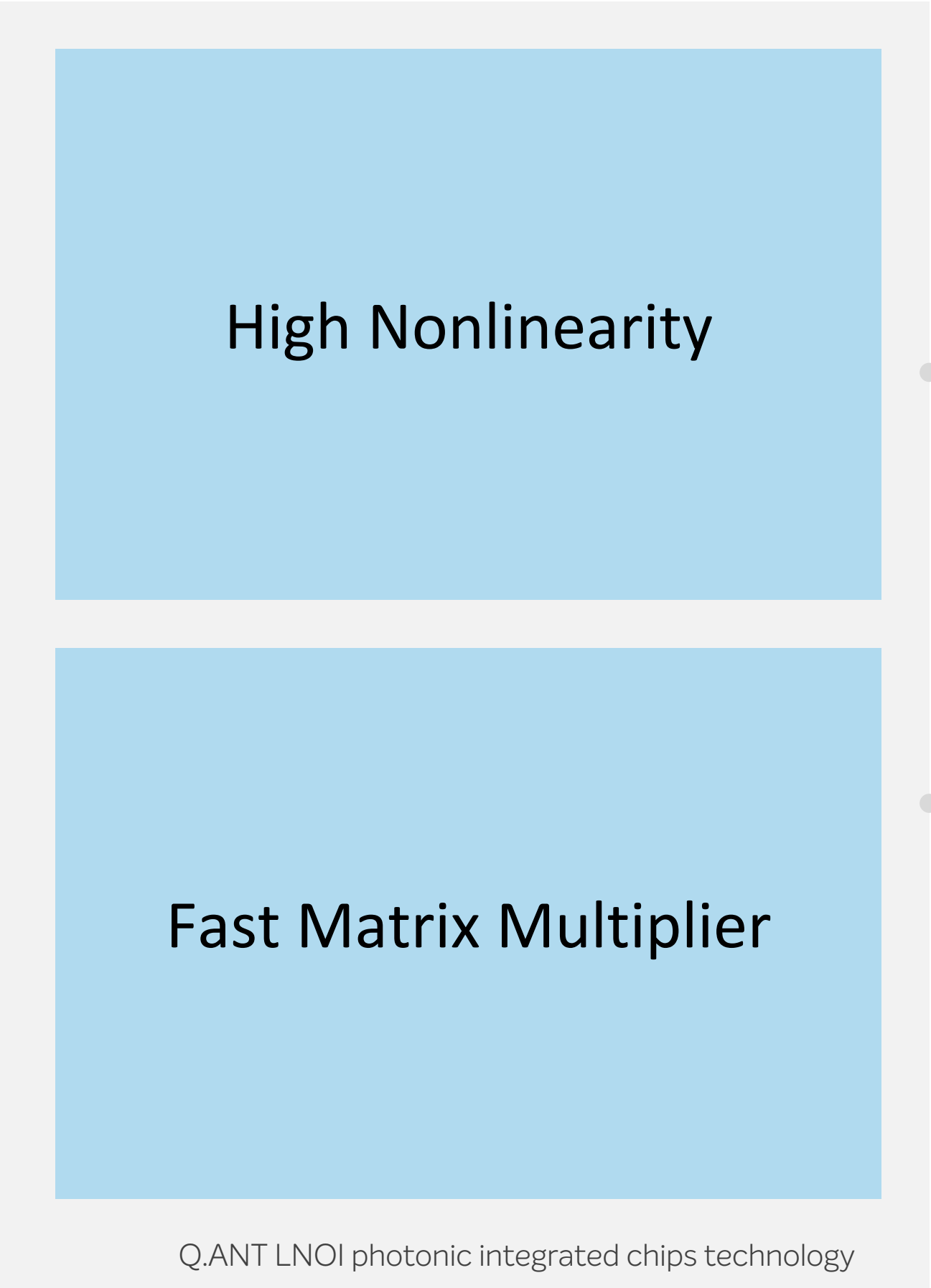


We can scale this up thanks to our photonic integrated circuit platform
to reach even higher levels on parallelism

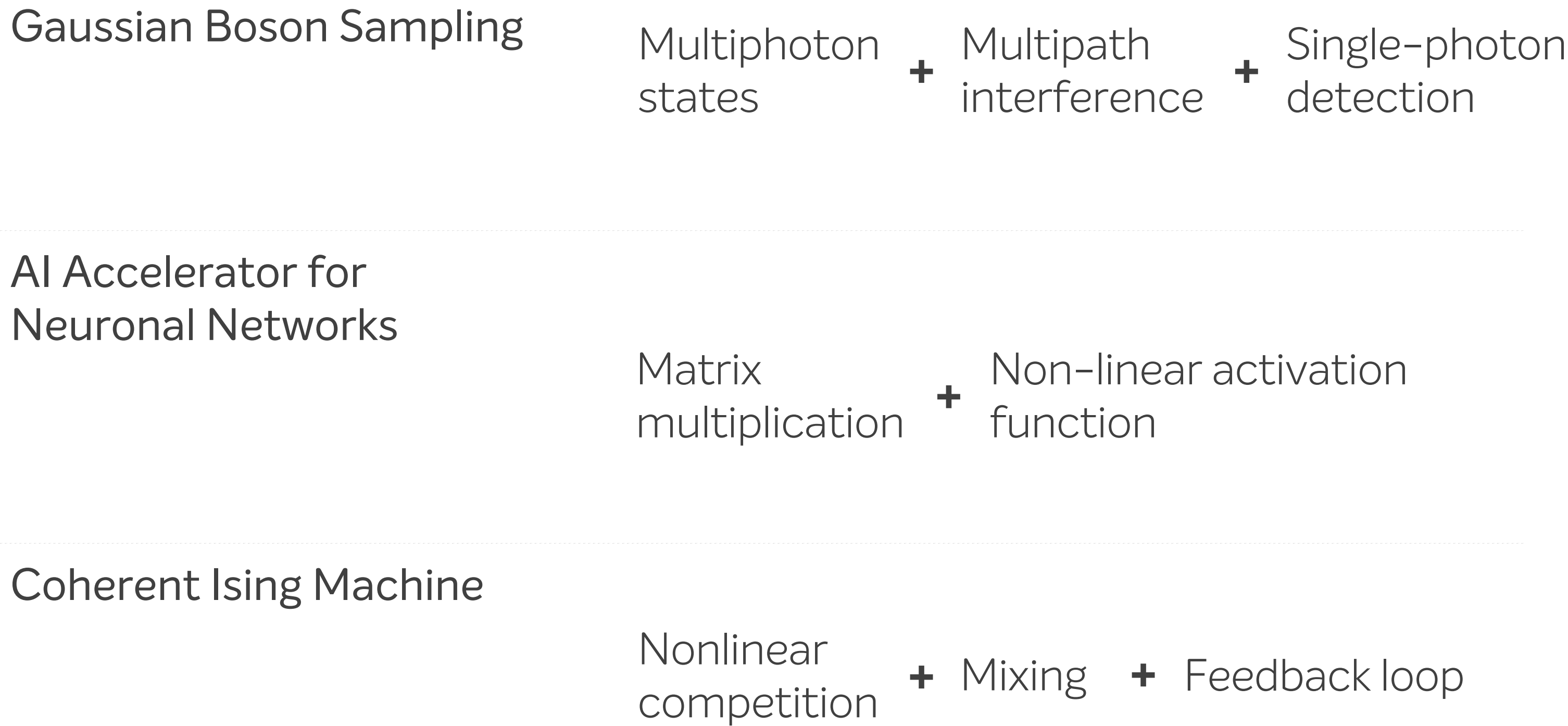


On a fundamental level, all applications require two features:
high nonlinearity combined and fast matrix multiplication.

Chip Features

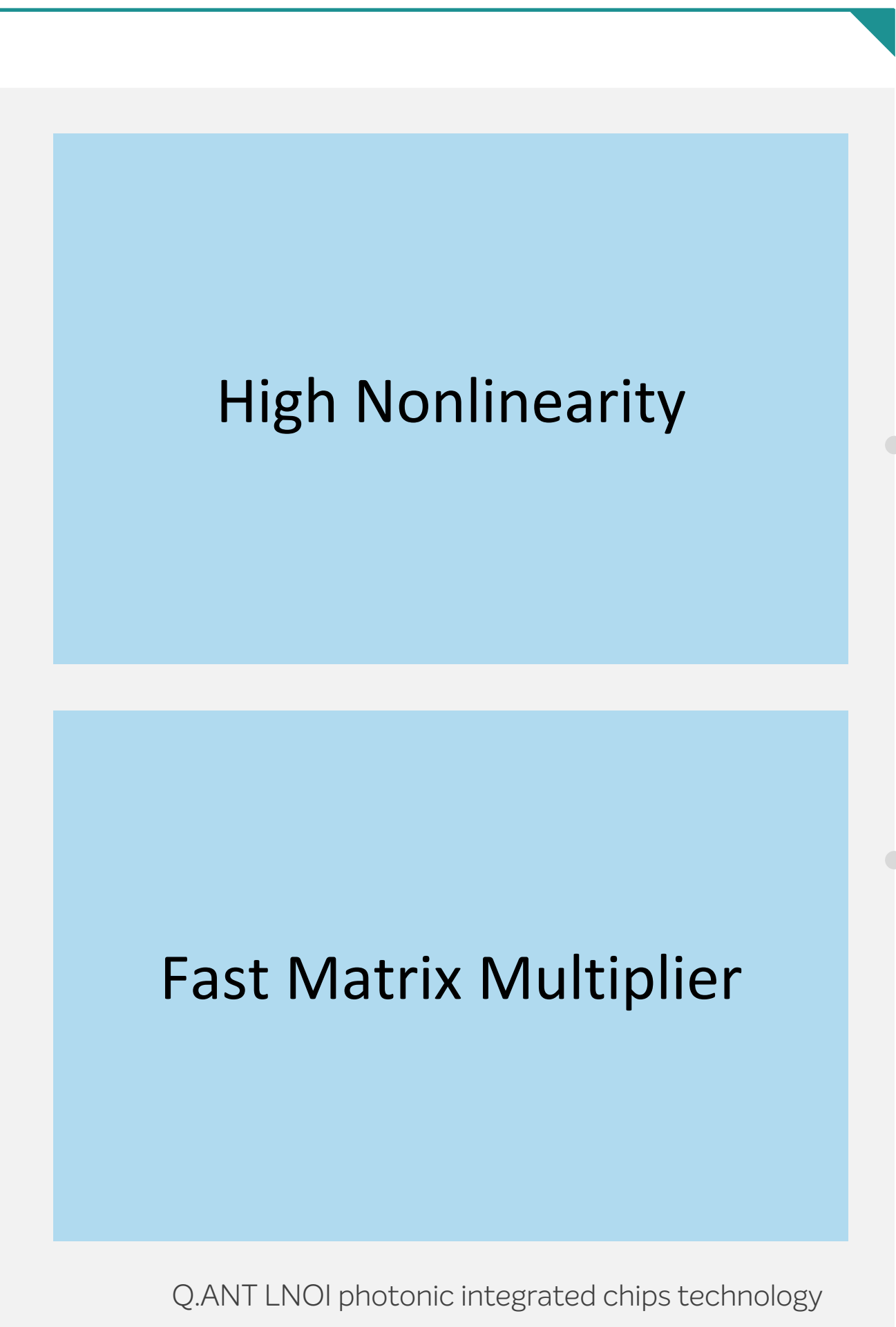


Chip Architecture



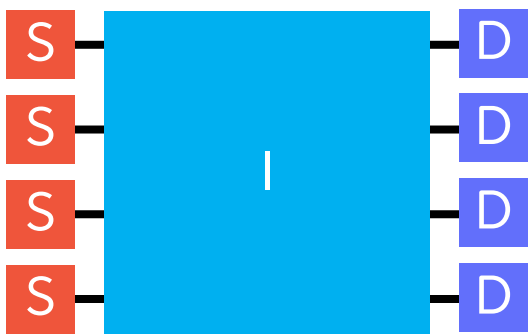
Q.ANT’s chip architecture is based on Lithium Niobate on Insulator (LNOI)
which combines both features: high nonlinearities with matrix multiplication.

Chip Features

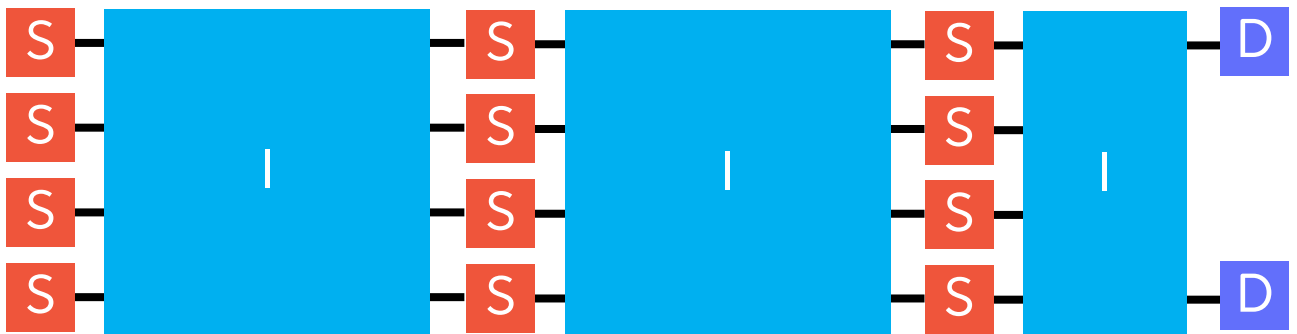


Chip Architecture

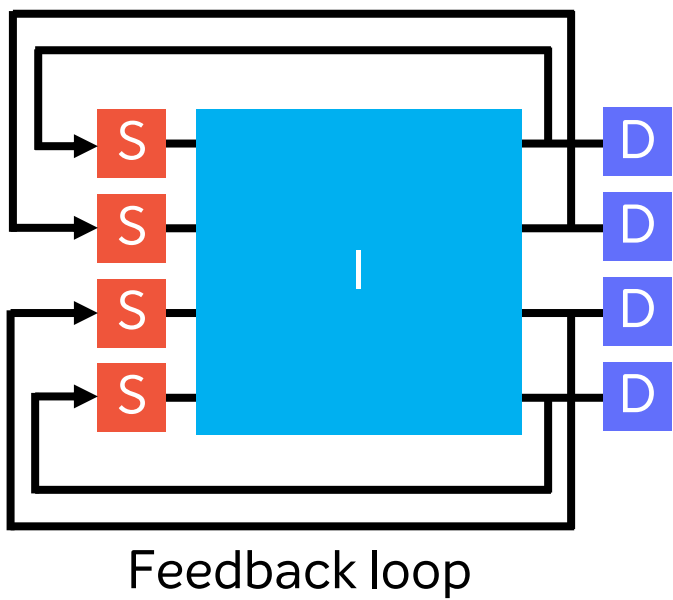
Gaussian Boson Sampling






AI Accelerator for
Neuronal Networks



Coherent Ising Machine



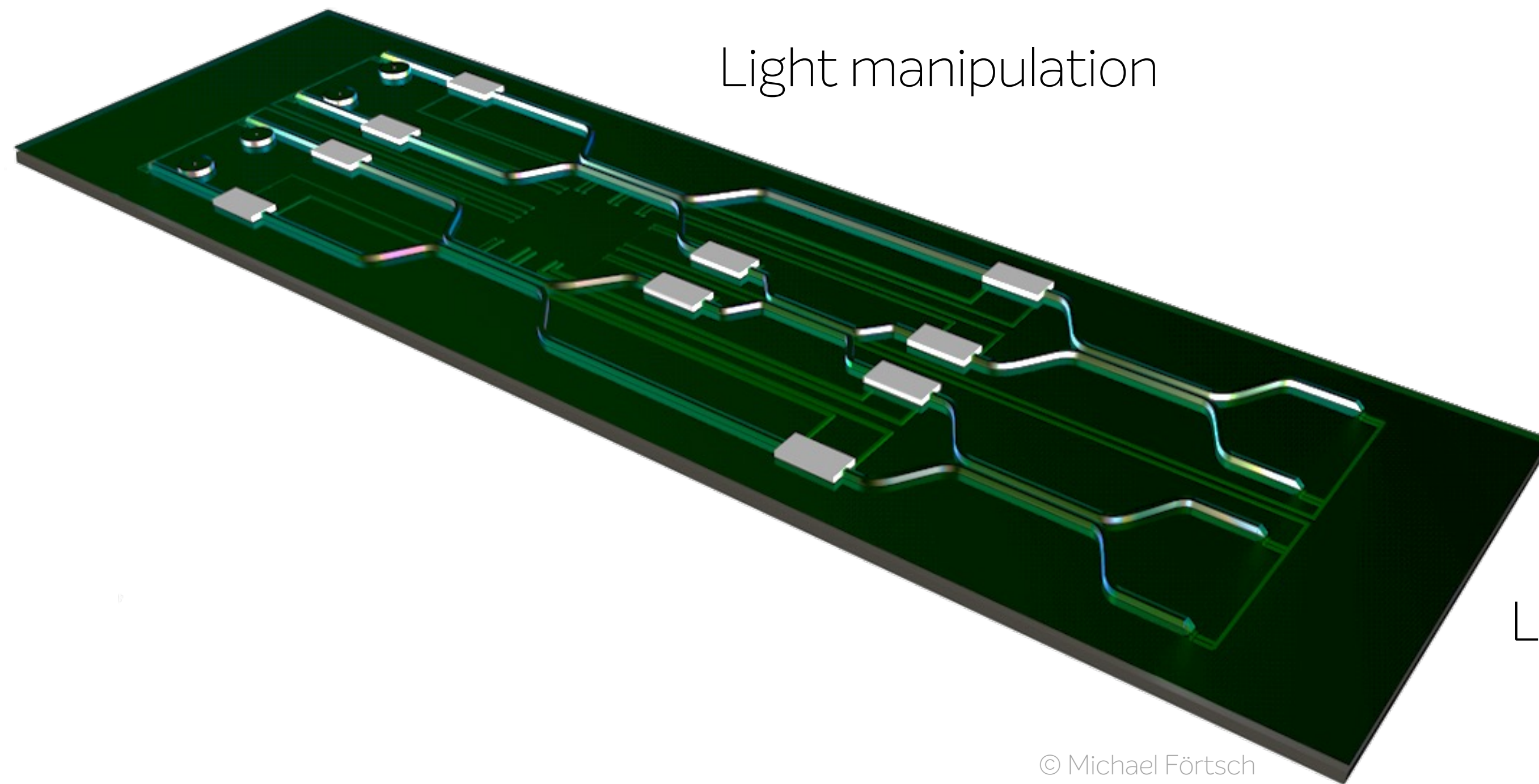
-  Squeezer (nonlinearity)
-  Interferometer (matrix mult.)
-  Detector

Q.ANT's chip architecture is based on Lithium Niobate on Insulator (LNOI)
which combines both features: high nonlinearities with matrix multiplication.

Light generation







Light manipulation

Light detection



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Q.ANT 2019

There is no photonic silicon – Multiple materials compete in integrated photonics.
LNOI/ TFLN has advantageous properties but is not standard Fab compatible.

	InP/ InGaAs	AlGaAs/ GaAs	Silicon/Ge	SiN	Polymers	Glass / Silica	LNOI / TFLN
Passive components	+	+	++	+++	+++	+++	+++ 
Polarization components	++	+	+	++	+	Hybrid	+++ 
Lasers	+++	++	Hybrid	Hybrid	Hybrid	Hybrid	Hybrid
Modulators	+++	Hybrid	+	Thermal	++	Hybrid / Thermal	+++ 
Switches	++	+	+	+	+	+	+++ 
Optical amplifiers	+++	+++	Hybrid	Hybrid	Hybrid	Hybrid	Hybrid
Detectors	+++	+++	++	Hybrid	Hybrid	Hybrid	Hybrid
Losses (dB/cm)	2	2	2	0.1	1.0	0.5	0.1 
2. order non-linearity	n.a.	n.a.	n.a.	n.a.	n.a.	n.a.	+++ 
Wafer-size	4"	3-6"	6-12"	6-12"	> 8"	6-12"	3-6"
Supply Chain	critical	critical	uncritical	uncritical	uncritical	uncritical	critical
PROs	Best for laser integration	Best for laser integration	CMOS compatible	Low cost Small size	Compatible with Si/InP platforms	Low cost	Very good modulation
CONS	High cost and low yield for components integrating other elements	High cost and low yield for components integrating other elements	No good optical material	Slow Modulators Material properties are process-dependent	Reliability/thermal management issues	No active functionalities	Not standard Fab compatible

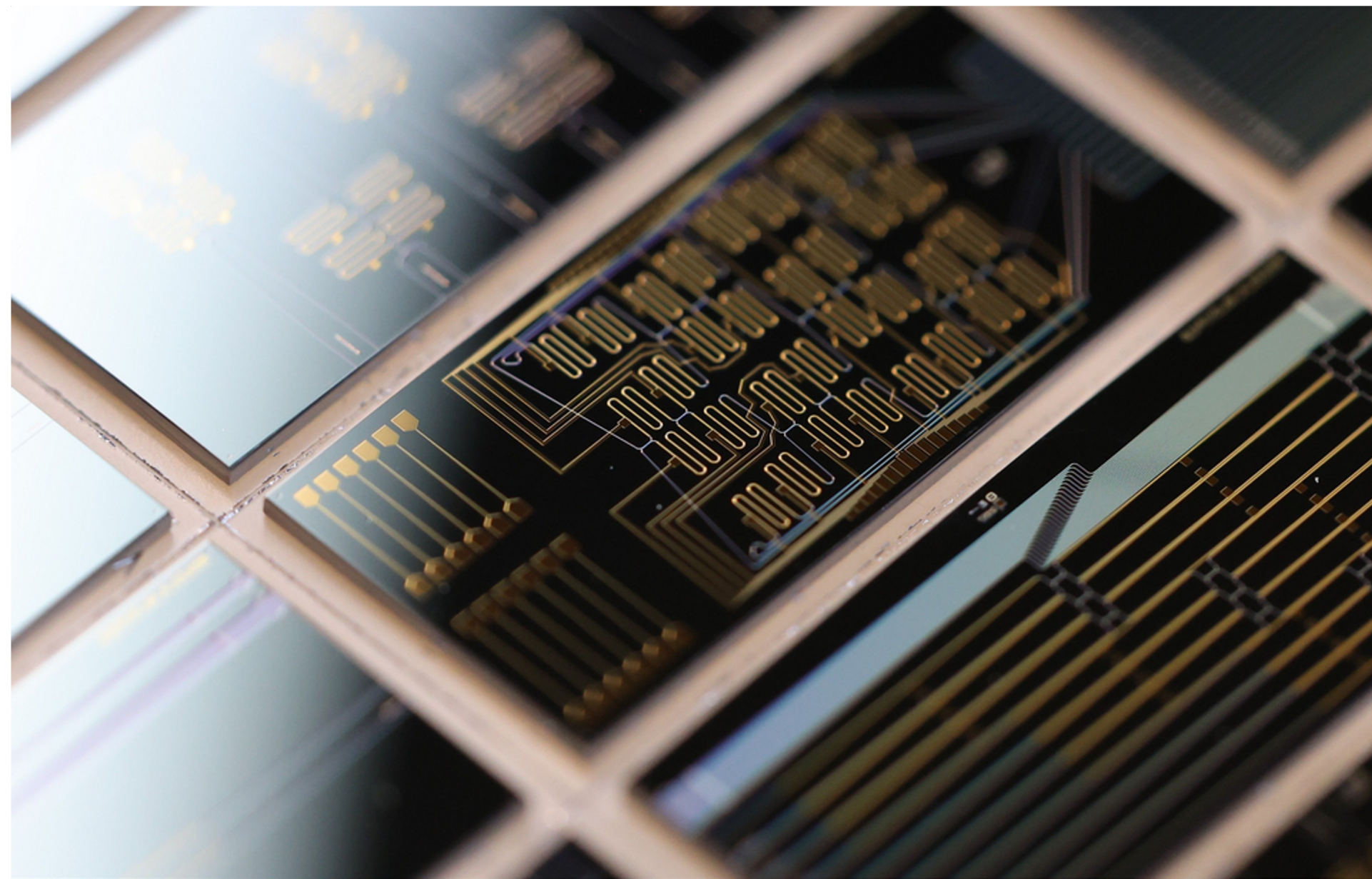
Source: Yole report; Expert interviews

+ Moderate performance ++ Good performance +++ Strong performance Hybrid Ability in combination with other PIC

Status June 2023: First 4 x 4 matrix chip realized, 20 x 20 in layout

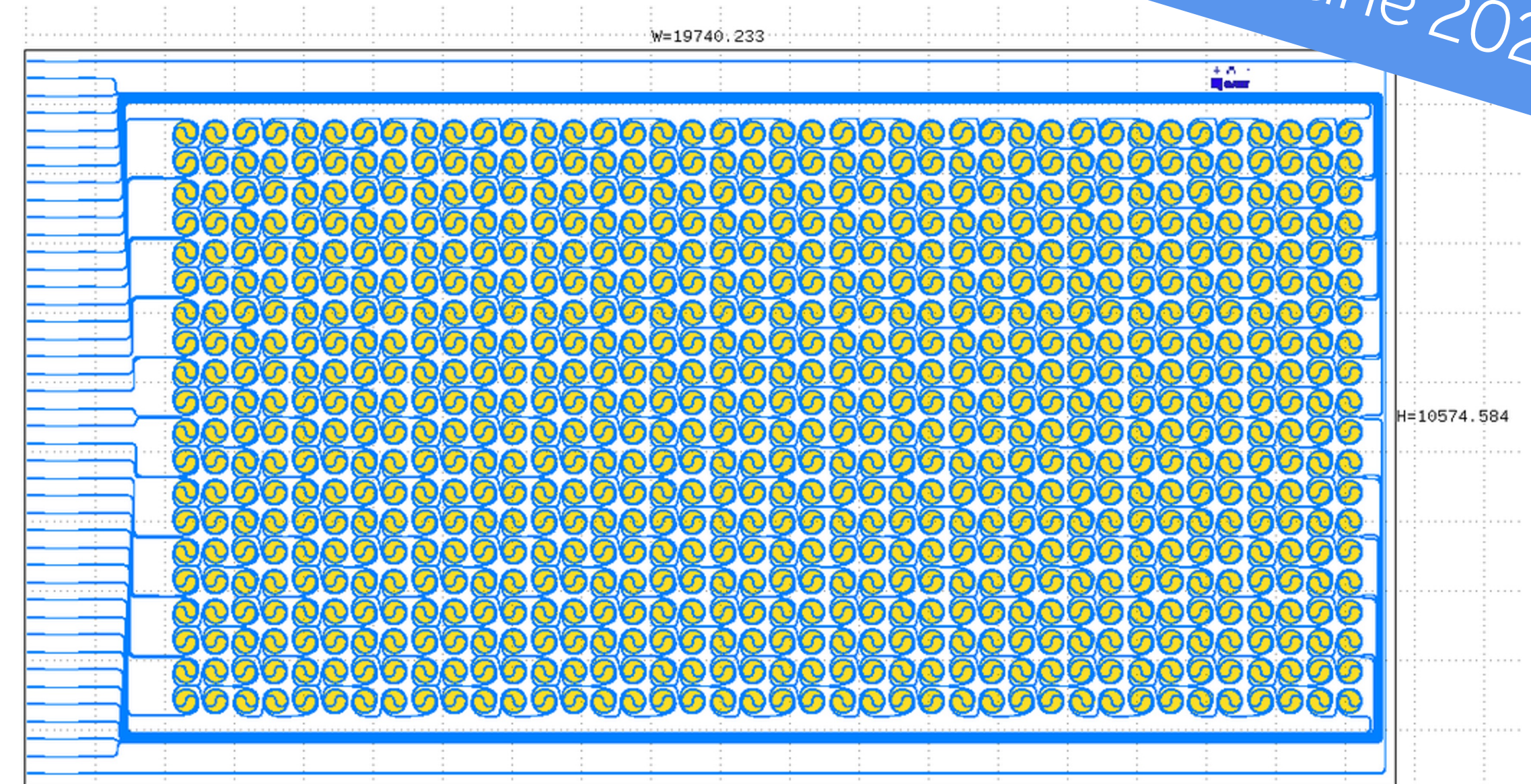
Fabrication status: 4 x 4 photonic integrated chip

Fabrication status: 4 x 4 photonic integrated chip



Layout status: 20 x 20 chip

Status June 2023



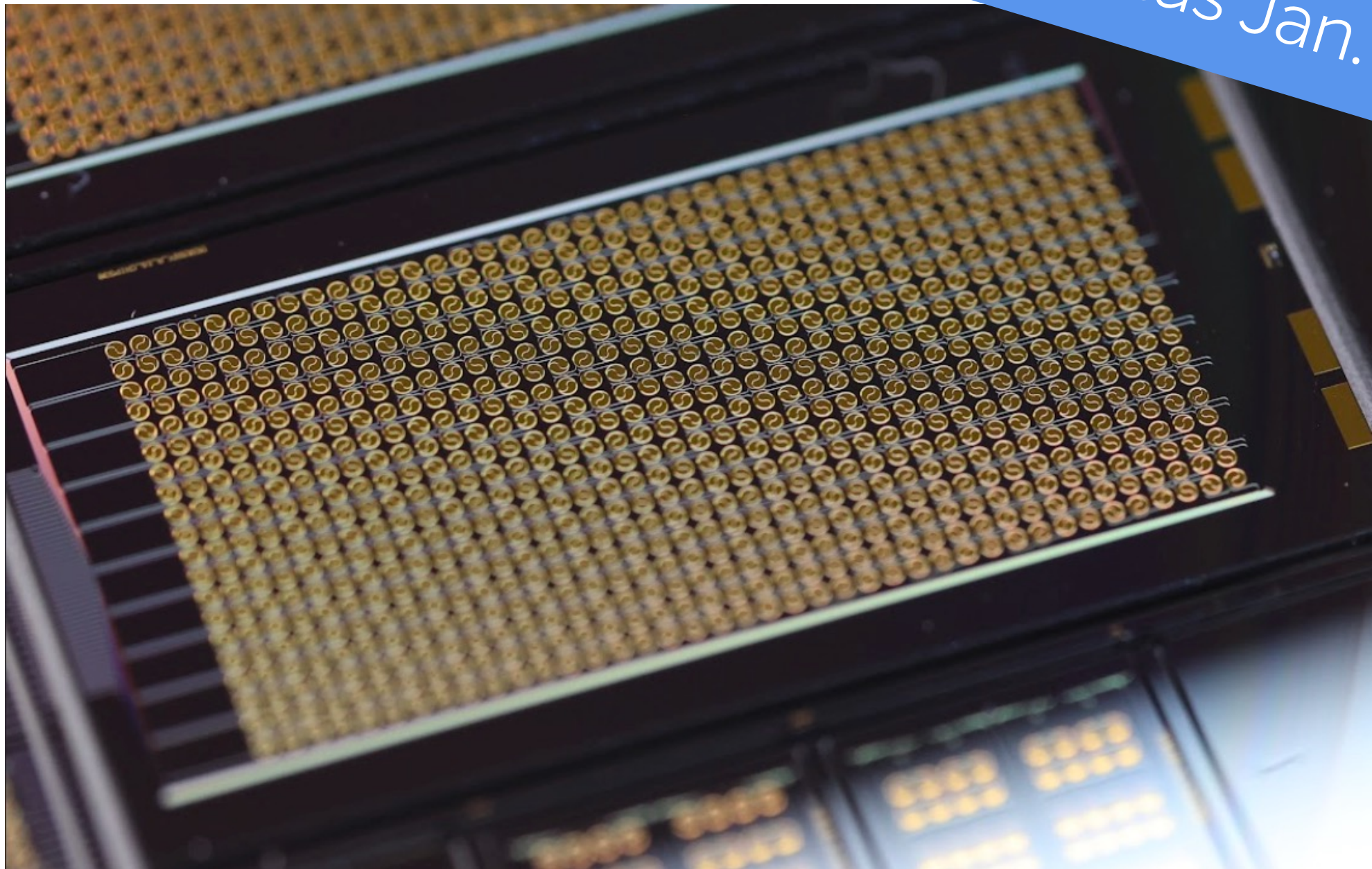
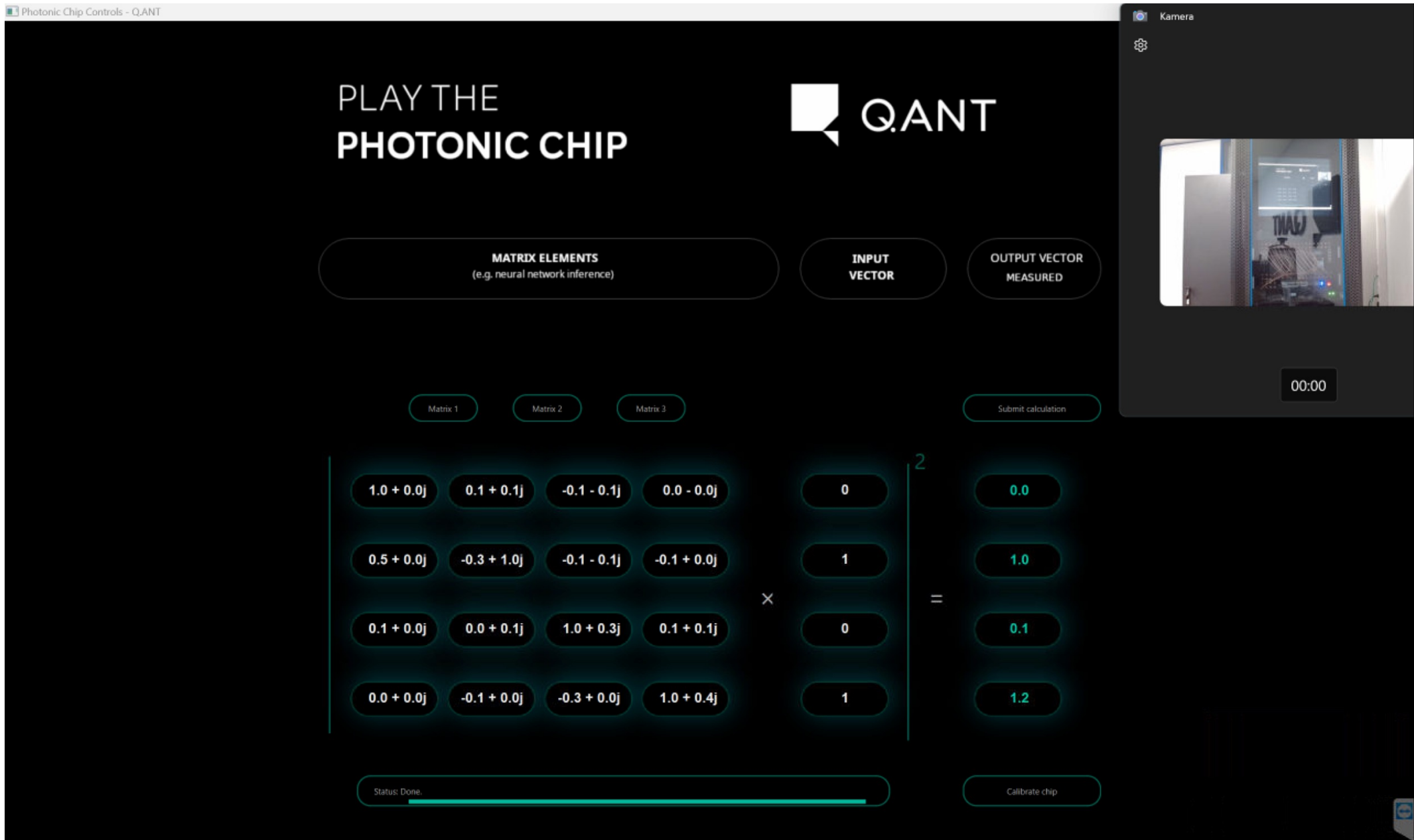
- Scaling to 20 x 20 matrix sizes is ongoing
- Key devices: MZMs with spiral-electrodes and fiber array inputs

Status Jan. 2024: First 4 x 4 processor realized, 20 x 20 chip manufactured
Processor presented at CadenceCONNECT ‘Rise of Photonic Computing’ (07. Feb. 24)

First 4 x 4 matrix-vector processor

20 x 20 chip is fabricated

Status Jan. 2024



Clock frequency: 1 MHz



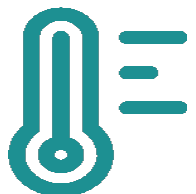
System power consumption: < 1kW @230V



Control: 2x5U 19“ Rack



Chip temperature: 22°C



Ambient temperature: +10°C ≤ T ≤ +40°C

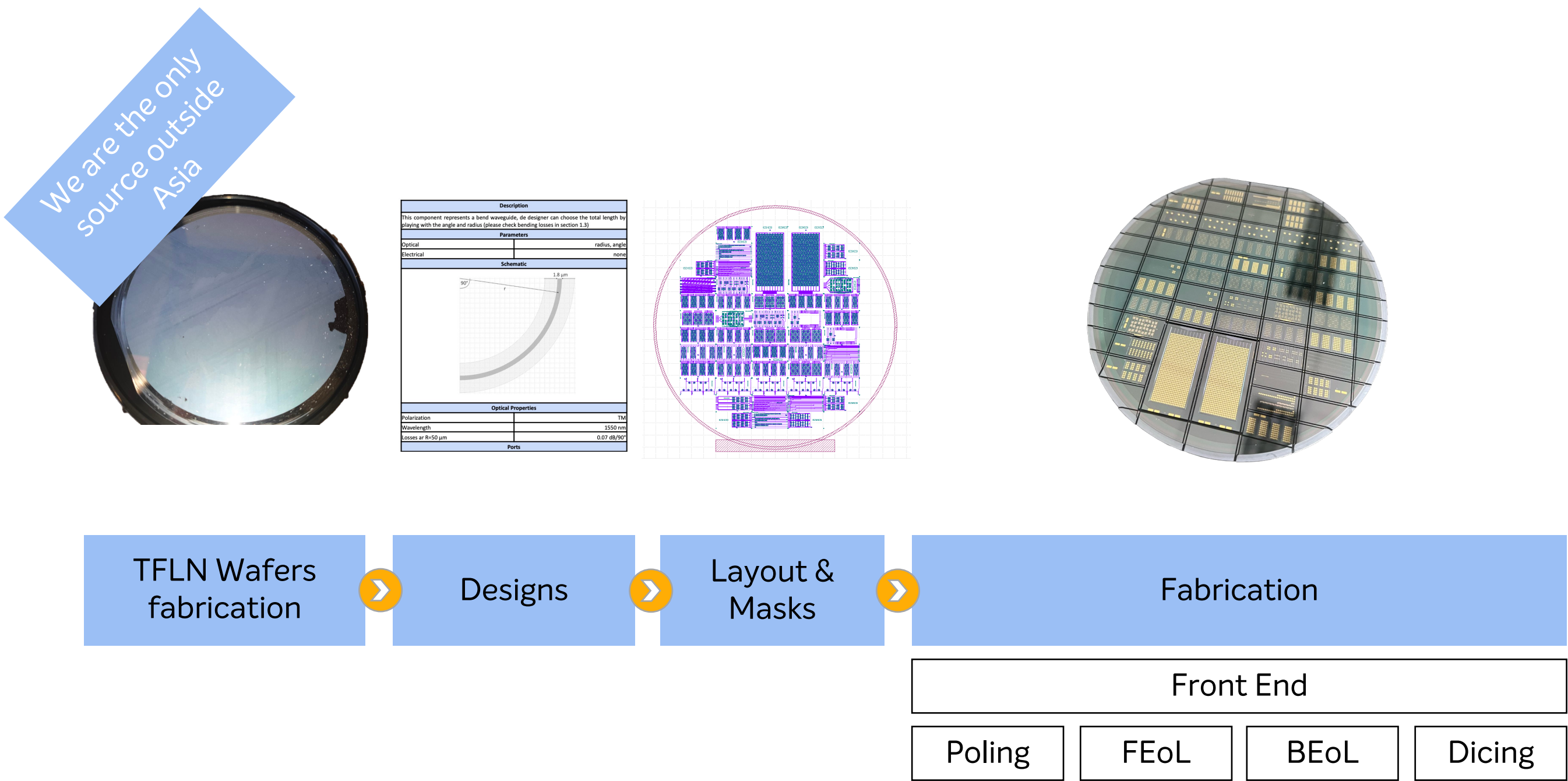


Availability: 2024

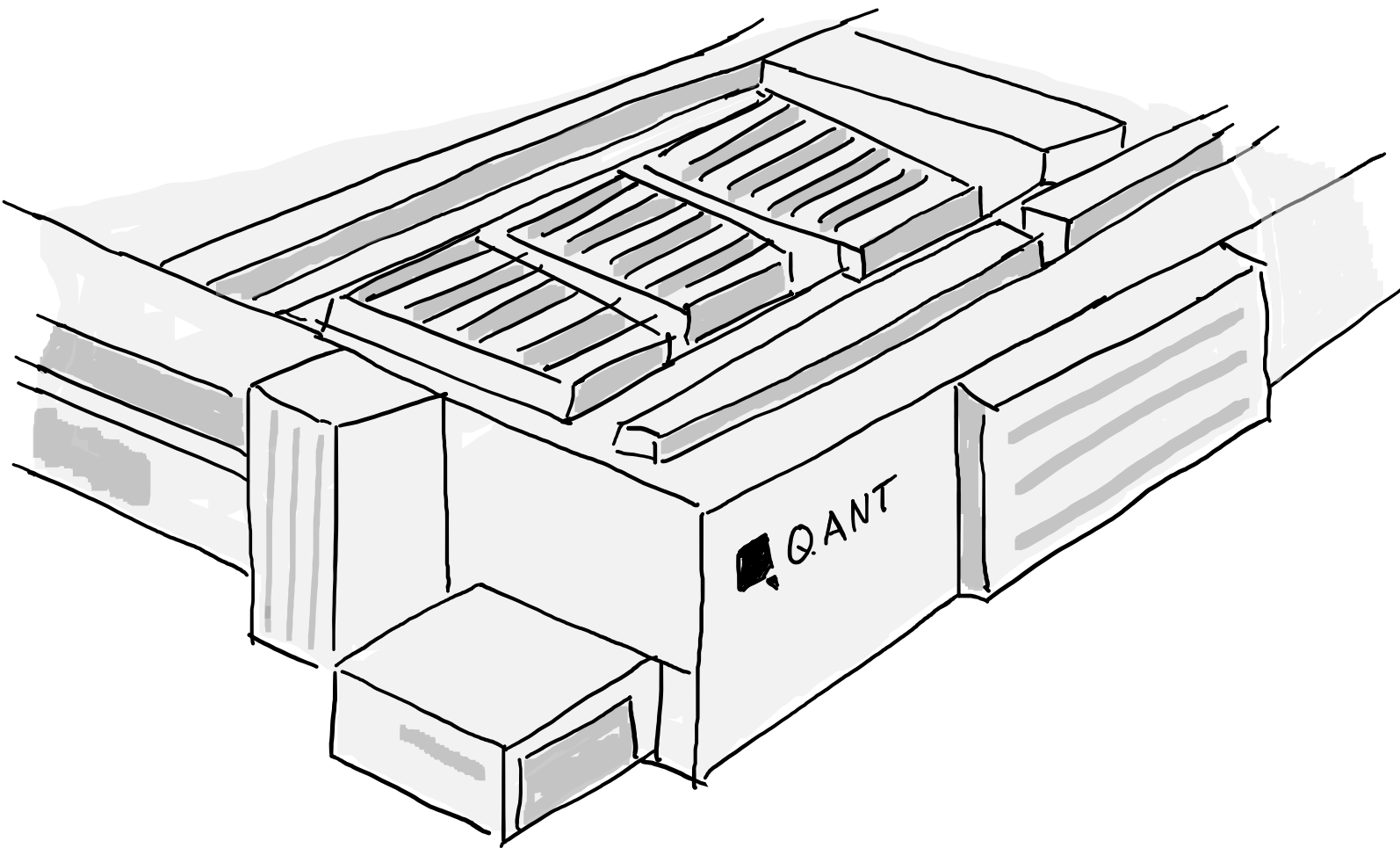
We have developed proprietary processes for TFLN PIC fabrication
and are now starting to bring everything together into our own pilot line by 2025.

We cover the essential parts of the PIC value chain

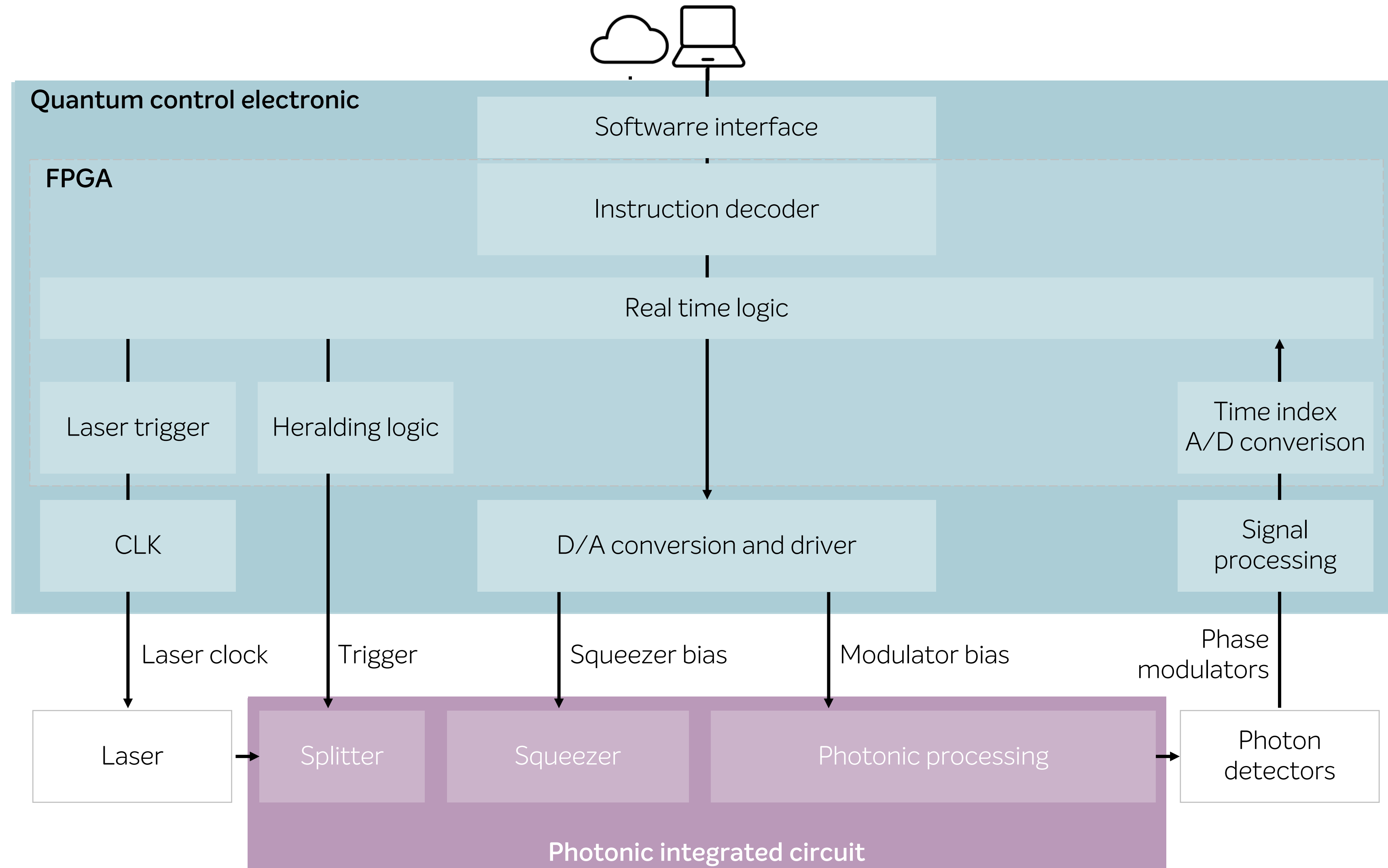
Own pilot fabrication line by 2025



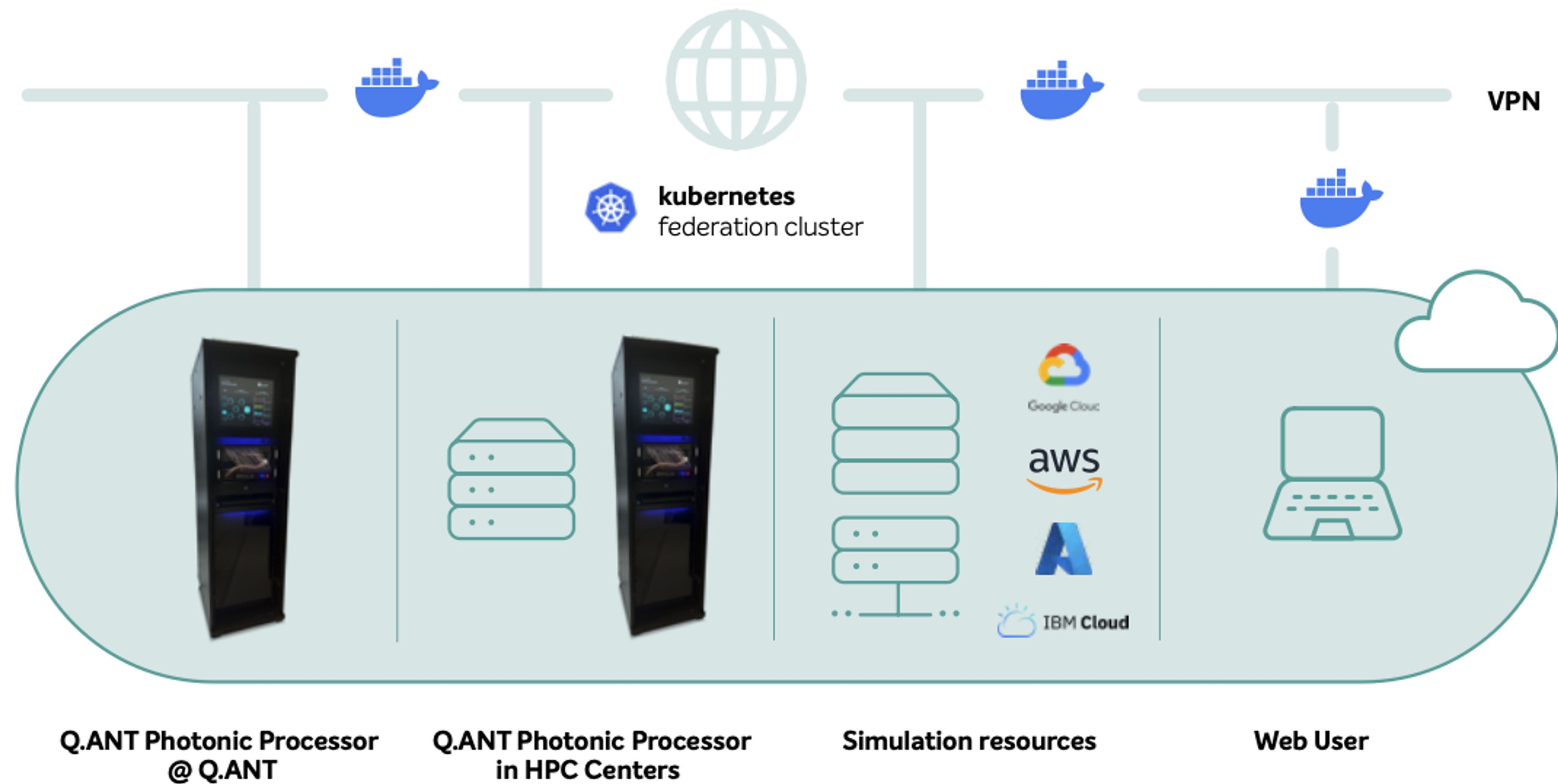
Partnership with IMS Chips



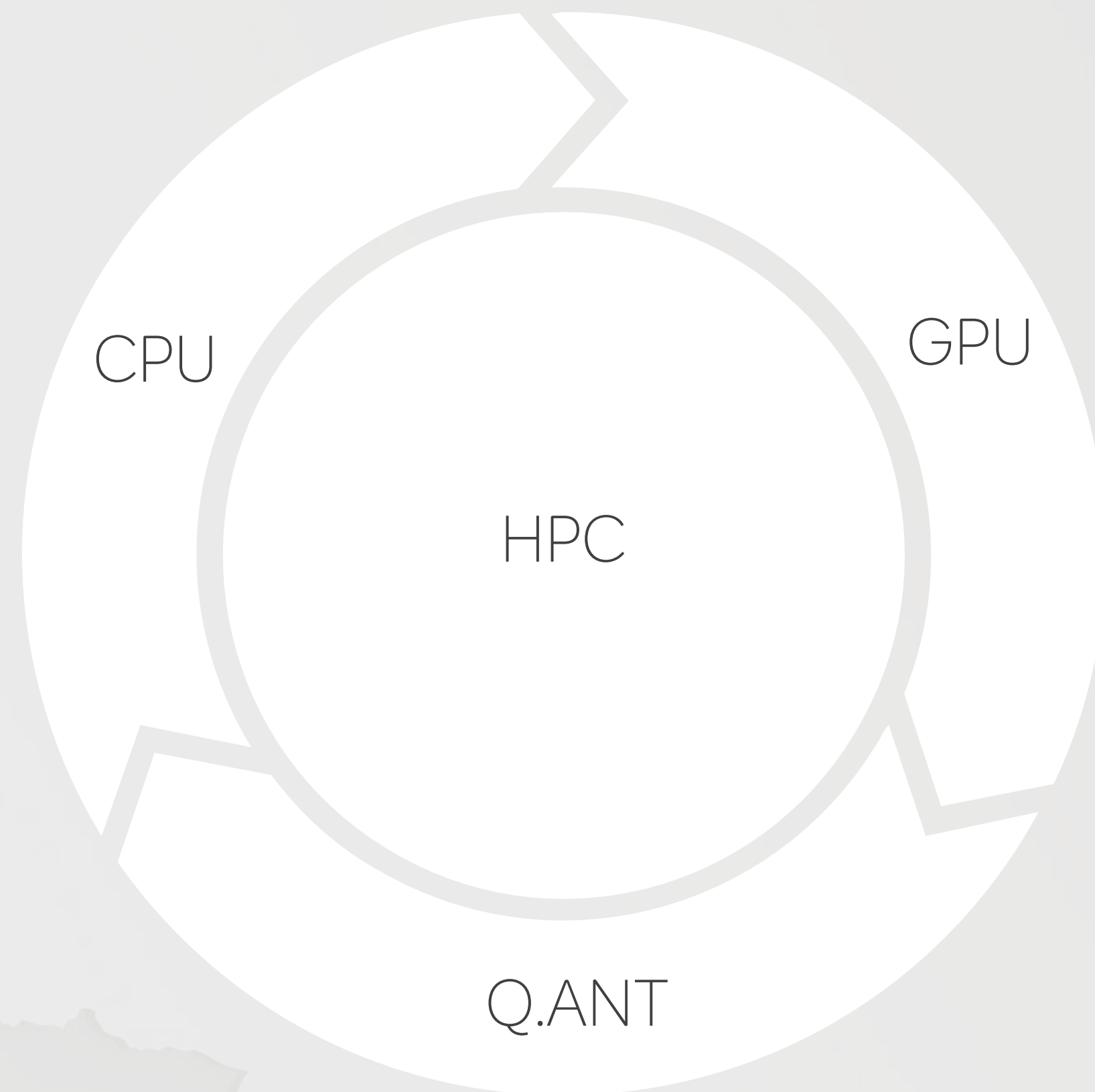
We deliver the complete photonic processor.



Our cloud computing infrastructure will provide easy access
thanks to the Q.ANT federation cluster.



Q.ANT processors will be part of High Performance Computing Centers



Applications

or how to get a share of the computing industry

Computing has three important figures of merit

Performance, Energy, and Cost



Performance

How fast can you solve a given task



Energy

How much energy is used for the task



Costs

What is the total cost of ownership

State of the art: Nvidia Blackwell B200

5000 TOPS (INT8)

1.200 W per card
0,24 TOP/J

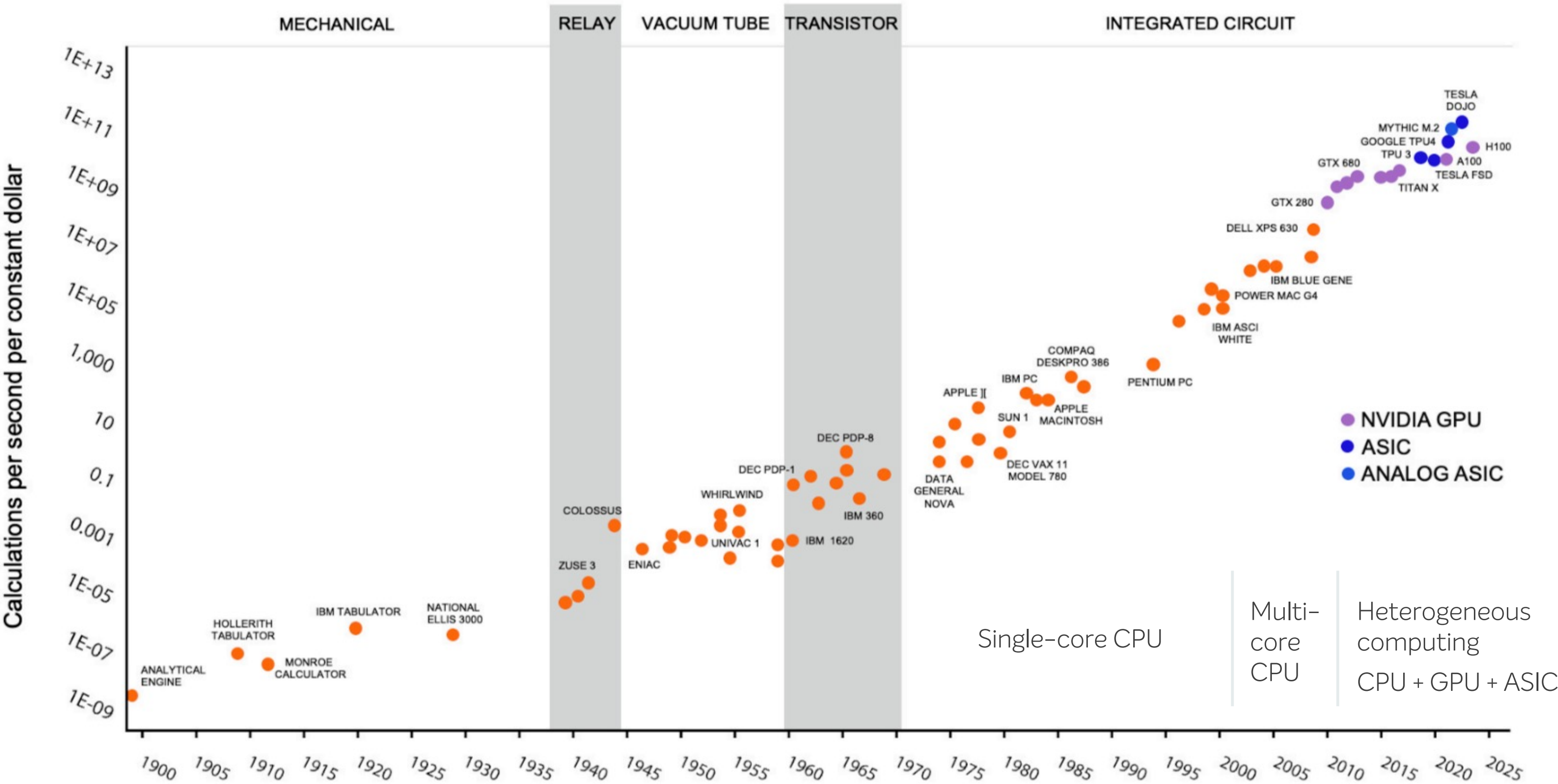
250 \$ per untested chip

TOPS = Tera Operations per Second // 1 Trillion operations per second
Source: NVIDIA Datasheet, TSMC Feb 18

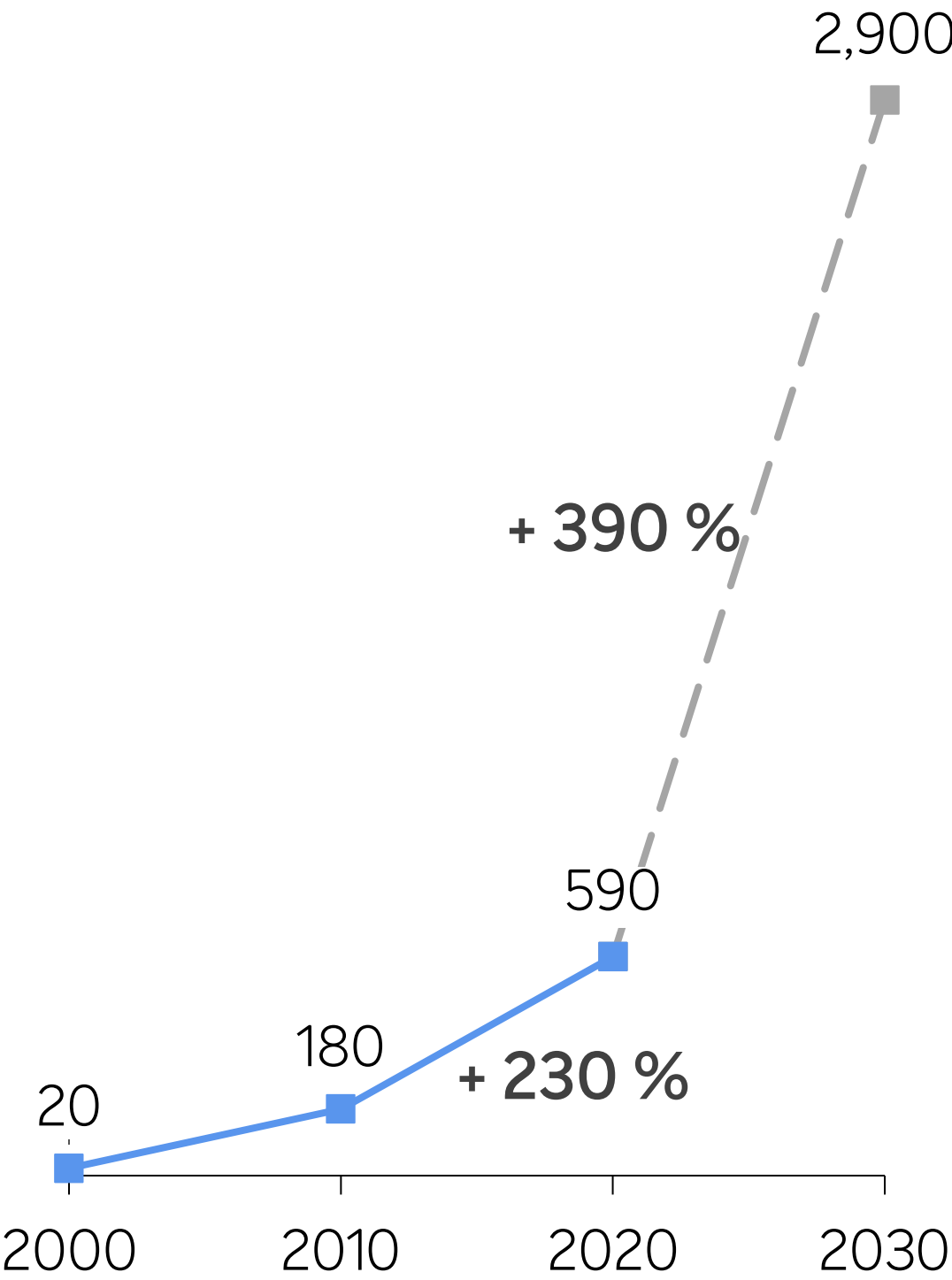
AI performance needs grow too fast compared to the hardware speed increase.
This requires additional calculation methods – photonics is supposed to support here.



125 YEARS OF MOORE’S LAW



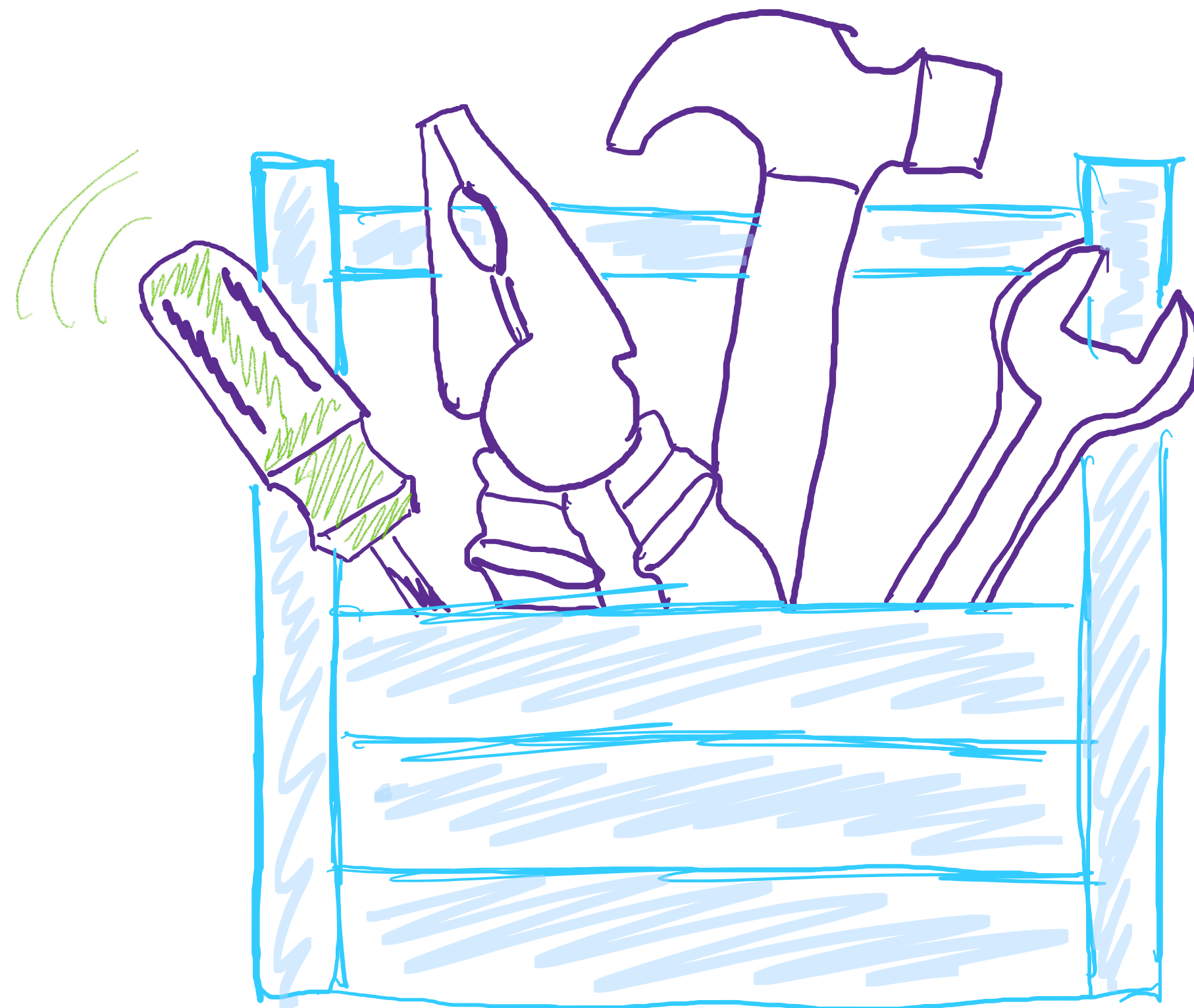
Energy consumption of data centers [TWh]



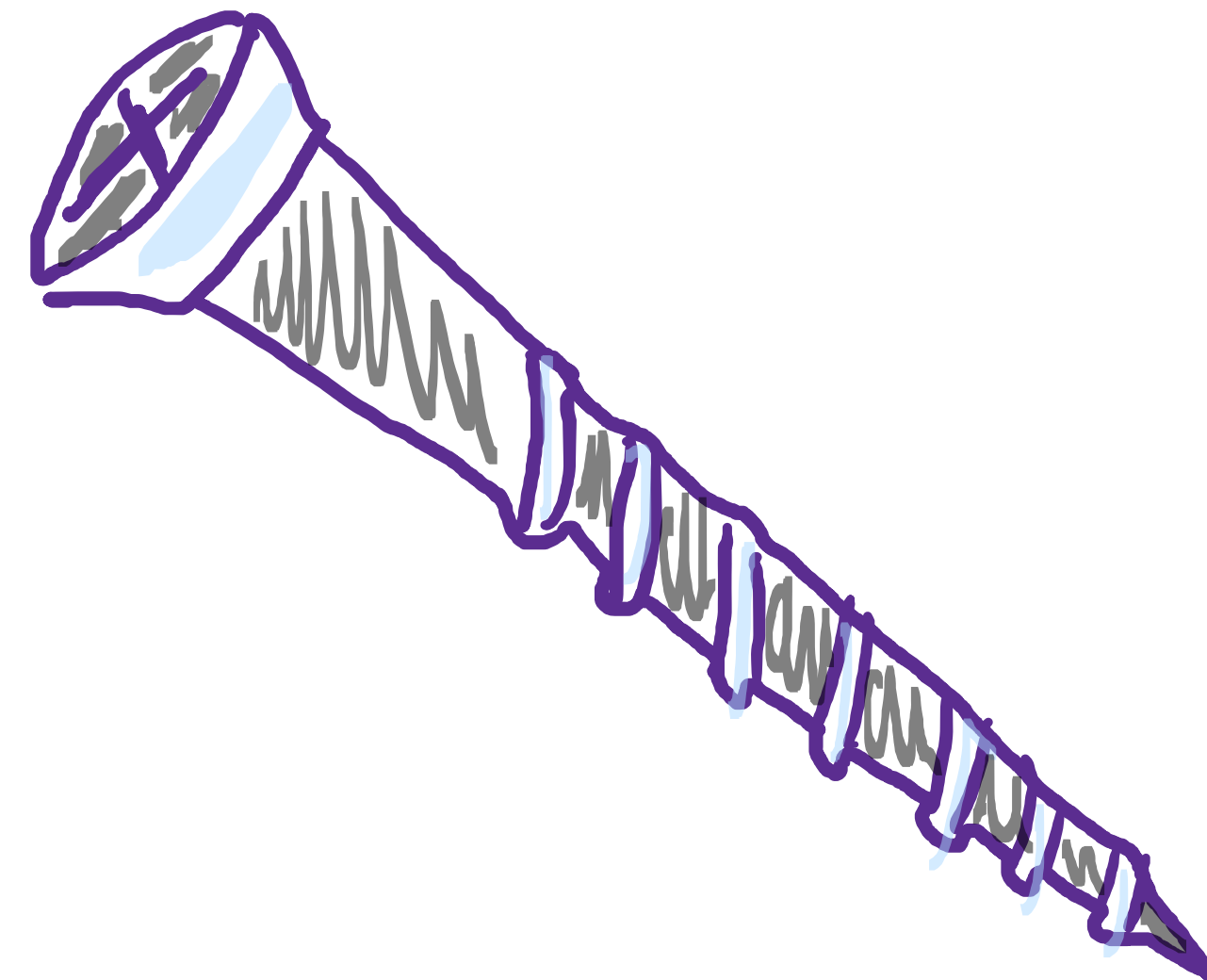
Ray Kurzweil & Steve Jurvetson, adapted from: https://www.reddit.com/r/singularity/comments/paszbd/122_years_of_moores_law_tesla_ai_update/
Katal, A., Dahiya, S. & Choudhury, T. Energy efficiency in cloud computing data center: a survey on hardware technologies. Cluster Comput 25, 675–705 (2022).

The present situation feels like using a hammer to push a screw into the wall.
 We must start looking at computing from the problem.

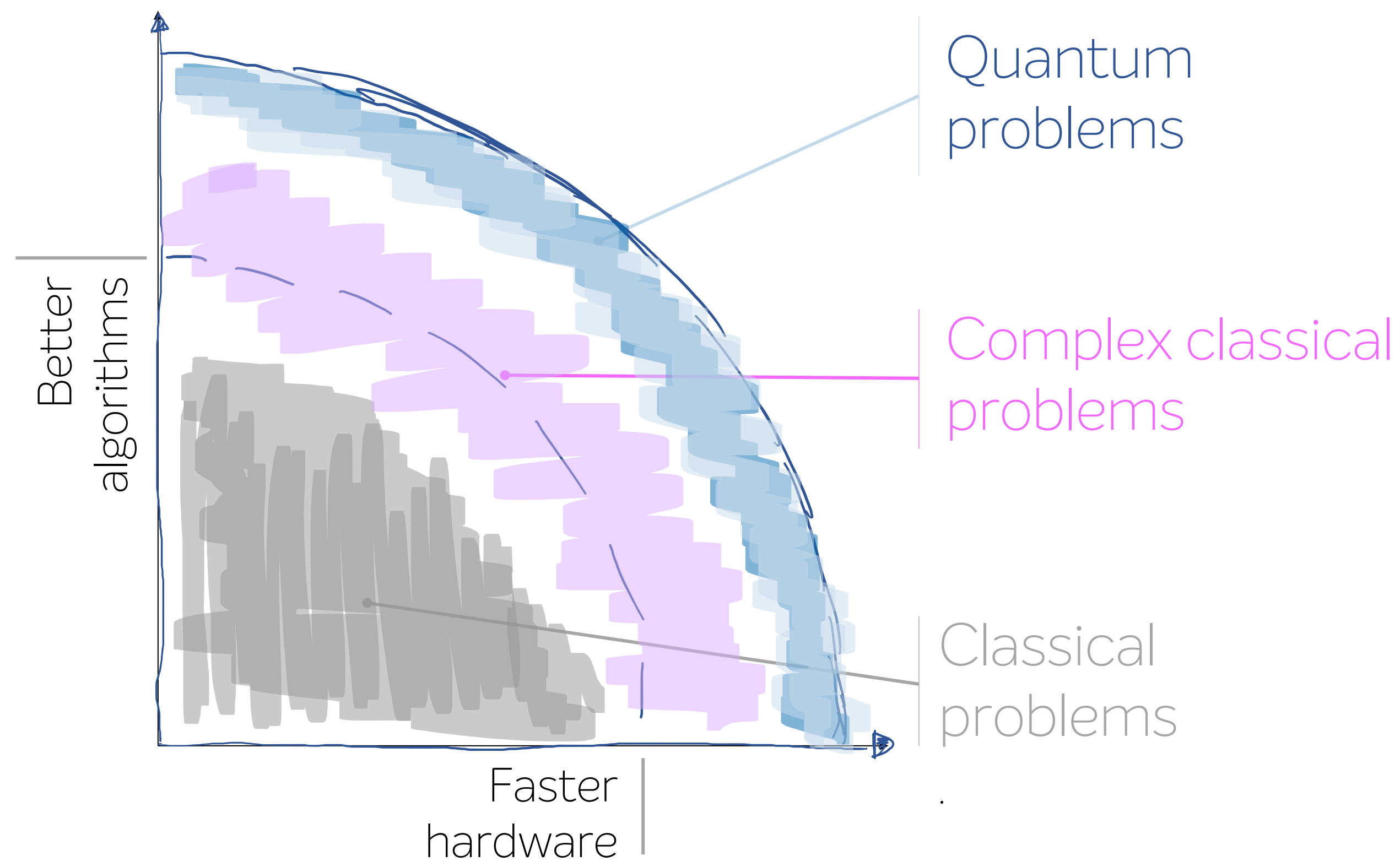
Product offering



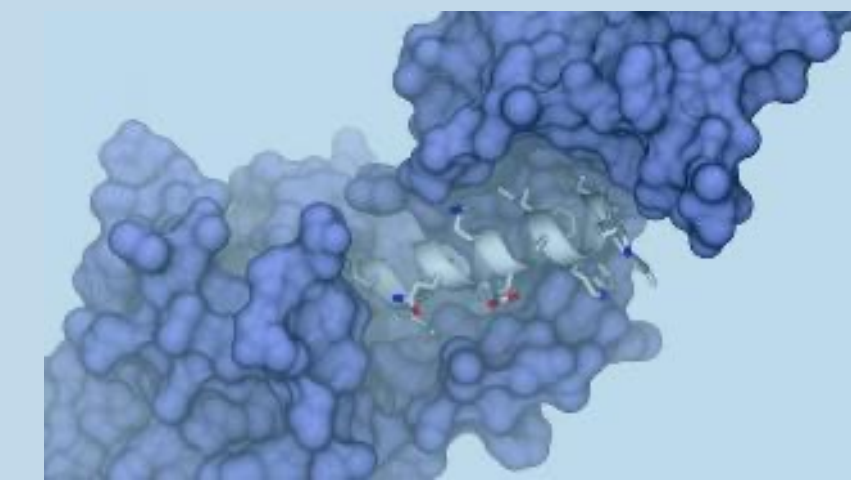
Customer needs



Quantum computing allows the calculation of today's unsolvable problems
which are either genuine quantum problems or complex classical problems.



Example in Drug Discovery:
Determine the electronic structure of the molecule



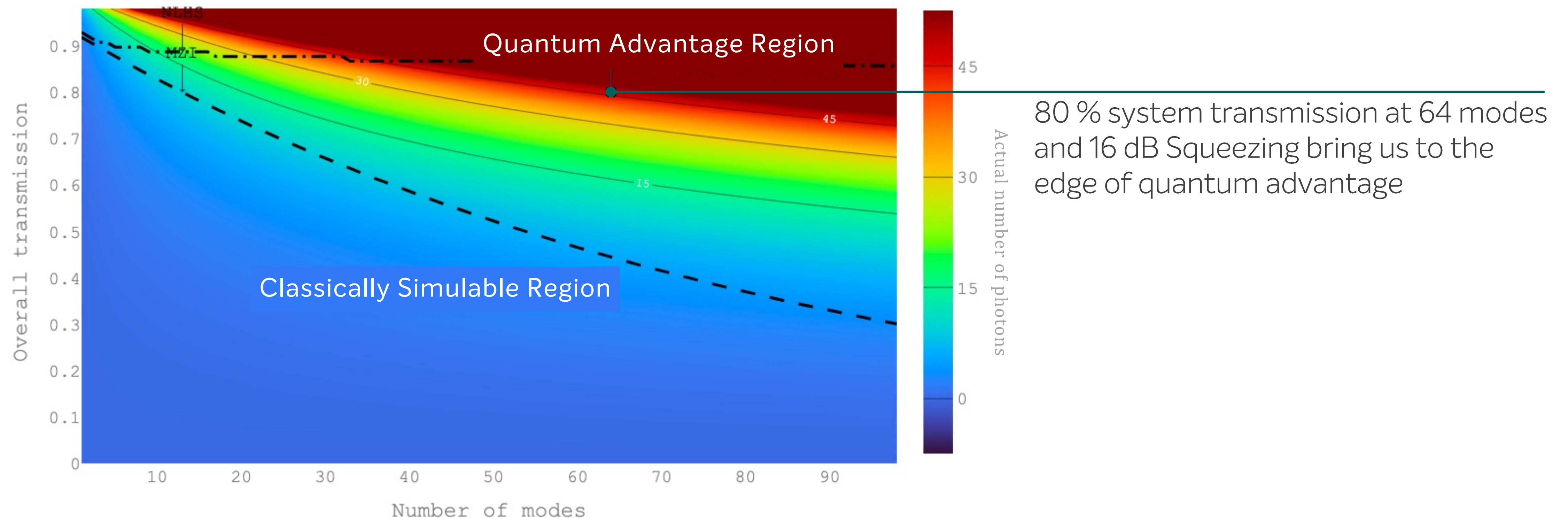
Picture: ProteinQure

Penicillin molecule has 41 atoms at ground state, modeling the structure requires:

- **Classical computer:** 10^{86} bits, such a machine is a *physical impossibility*
- **QComputer:** 286 logical quantum bits (Qubits)

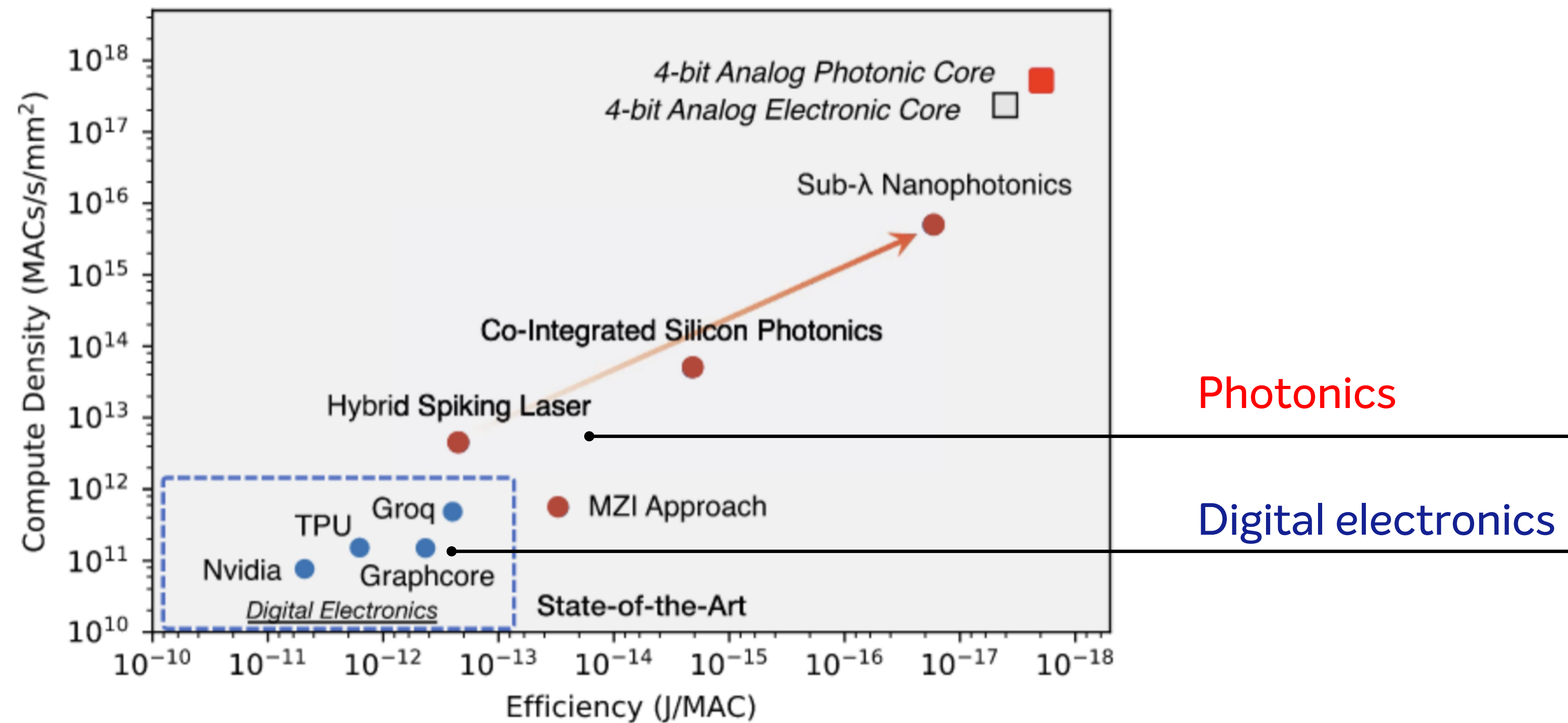
Quantum advantage on Gaussian Boson Samplers requires high transmission which we believe can only be achieved in a fully integrated system.

Estimation of quantum advantage of GBS against classical Tensor Network methods



Go, et al. "Exploring Shallow-Depth Boson Sampling: Towards Scalable Quantum Supremacy." arXiv:2306.10671 (2023)
Oh. "Classical algorithm for simulating experimental Gaussian boson sampling." Bulletin of the American Physical Society (2024)

Photonics can be very efficient in Multiply-Accumulate Operations compared to state-of-the-art semiconductor AI accelerators



Nahmias et. al, "Photonic Multiply-Accumulate Operations for Neural Networks," in IEEE Journal of Selected Topics in Quantum Electronics, vol. 26 (2020),

The power consumption is one great advantages of our LNOI chip architecture.
The main power consumers are not on the chip!

Work in progress

System Performance Parameters – preliminary

	Proof-of-concept demo	Matrix vector multiplier (MVM) Generation 1	MVM Generation 2
Release	Feb. 2024	Aug. 2024	2025
DAC Precision	10 bits	12 bits	10 bits
Matrix size	4 x 4	4 x 4	16 x 16
Power consumption	11 W	20 W	150 W
Performance	0.14 OPS	28 MOPS	496 GOPS
Efficiency	80 W / OP	< 700 nW / OP	< 300 pW / OP

Advancements of Para.Digm realizes a roadmap from vector-matrix, to training to Quantum

Processor Three

Quantum

Closed-loop training

Processor Two

Training

Streaming and non-linearities
for AI applications

Processor One

Streaming

Vector matrix multiplication for AI
acceleration



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